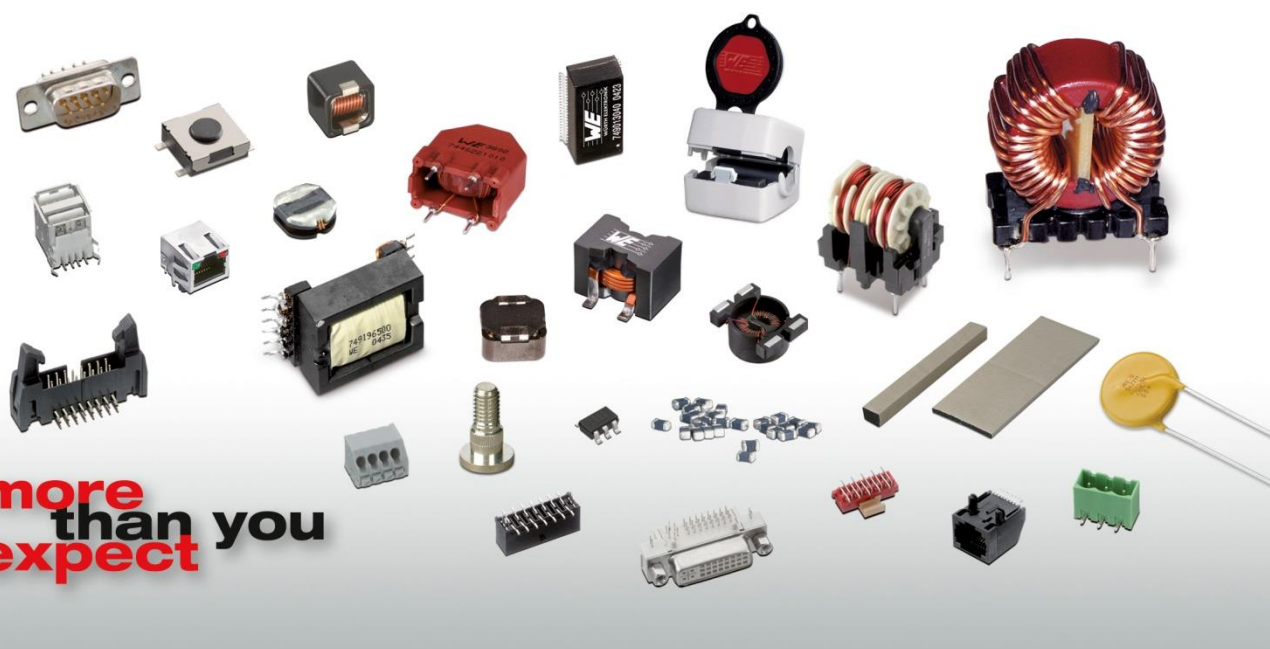




USB 3.1 C Technical Analysis and Design Tips



**more
than you
expect**

**Würth Elektronik
Timo Dreyer**

Table of Content

- Why Type USB 3.1 & Type C
- History of USB and Evolution
- Electrical Performance
- Mechanical Performance
- RF Behaviour
- Conclusion





Why Type USB 3.1 & Type C

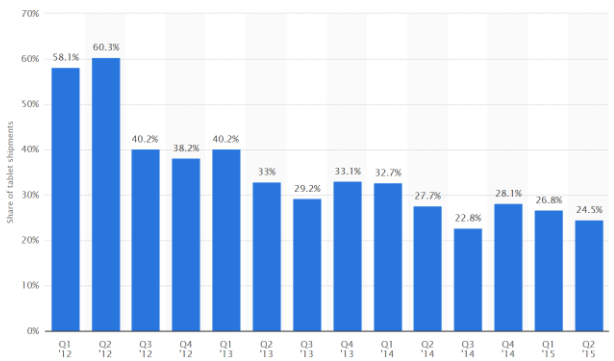
Market trends for USB (3.1)

➤ Telecommunications & entertainment

➤ Smartphones:

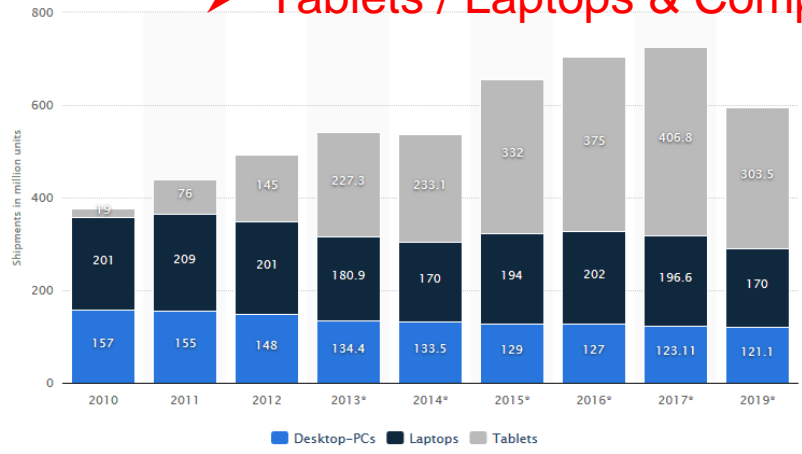
In Q2 2015, Apple has “only” 24,5% of market share with Iphone with their lightning connector.

The statistic shows the market share of Apple of global tablet shipments from the first quarter of 2012 to the second quarter of 2015. In the fourth quarter of 2013 Apple's market share was at 33.2 percent.



Moreover, market will constantly grow:
+ 34% users from 2015 to 2018

➤ Tablets / Laptops & Computers: For 2016 + 2017:



- Tablets: 782 kk units (+22 %)
- Laptops: 399 kk units (+ 2 %)
- Computers: 250 kk units (-5%)

Top 25 Countries, Ranked by Smartphone Users, 2013-2018

millions

	2013	2014	2015	2016	2017	2018
1. China*	436.1	519.7	574.2	624.7	672.1	704.1
2. US**	143.9	165.3	184.2	198.5	211.5	220.0
3. India	76.0	123.3	167.9	204.1	243.8	279.2
4. Japan	40.5	50.8	57.4	61.2	63.9	65.5
5. Russia	35.8	49.0	58.2	65.1	71.9	76.4
6. Brazil	27.1	38.8	48.6	58.5	66.6	71.9
7. Indonesia	27.4	38.3	52.2	69.4	86.6	103.0
8. Germany	29.6	36.4	44.5	50.8	56.1	59.2
9. UK**	33.2	36.4	39.4	42.4	44.9	46.4
10. South Korea	29.3	32.8	33.9	34.5	35.1	35.6
11. Mexico	22.9	28.7	34.2	39.4	44.7	49.9
12. France	21.0	26.7	32.9	37.8	41.5	43.7
13. Italy	19.5	24.1	28.6	32.2	33.7	37.0
14. Turkey	15.3	22.6	27.8	32.4	37.2	40.7
15. Spain	18.9	22.0	25.0	26.9	28.4	29.5
16. Philippines	14.8	20.0	24.8	29.7	34.8	39.4
17. Nigeria	15.9	19.5	23.1	26.8	30.5	34.0
18. Canada	15.2	17.8	20.0	21.7	23.0	23.9
19. Thailand	14.4	17.5	20.4	22.8	25.0	26.8
20. Vietnam	12.4	16.6	20.7	24.6	28.6	32.0
21. Egypt	12.6	15.5	18.2	21.0	23.6	25.8
22. Colombia	11.7	14.4	16.3	18.2	19.7	20.9
23. Australia	11.4	13.2	13.8	14.3	14.7	15.1
24. Poland	9.4	12.7	15.4	17.4	19.4	20.8
25. Argentina	8.8	10.8	12.6	14.1	15.6	17.0

Worldwide*** 1,311.2 1,639.0 1,914.6 2,155.0 2,380.2 2,561.8

Note: individuals of any age who own at least one smartphone and use the smartphone(s) at least once per month; *excludes Hong Kong; **forecast from Aug 2014; ***includes countries not listed

Source: eMarketer, Dec 2014

182905 www.eMarketer.com

Sources: <http://www.emarketer.com> & <http://www.statista.com>

Date 26.10.2017 | Technical Academy | Public | USB 3.1 C

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www.we-online.com

Why Type USB 3.1 & Type C

Market trends for USB (3.1)

➤ Storage / USB Sticks:

- Annual shipment of USB sticks could reach 556 kk units in 2020
- US Biggest market
- +8% growth is expected for Asia / Pacific area

➤ Power supply:

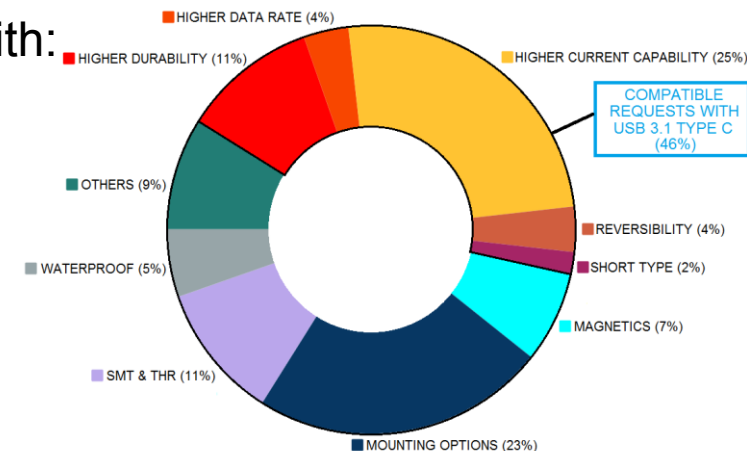
USB connectors are more and more often used as power suppliers:

- Customers are asking for high current connectors (1.8A / 2.1A & 3A)
- Smartphones, tablets, navigation systems are always requesting more & more power and need to be charged faster

➤ Survey on 90 WE customers in America:

USB 3.1 Type C fits with customers' expectations with:

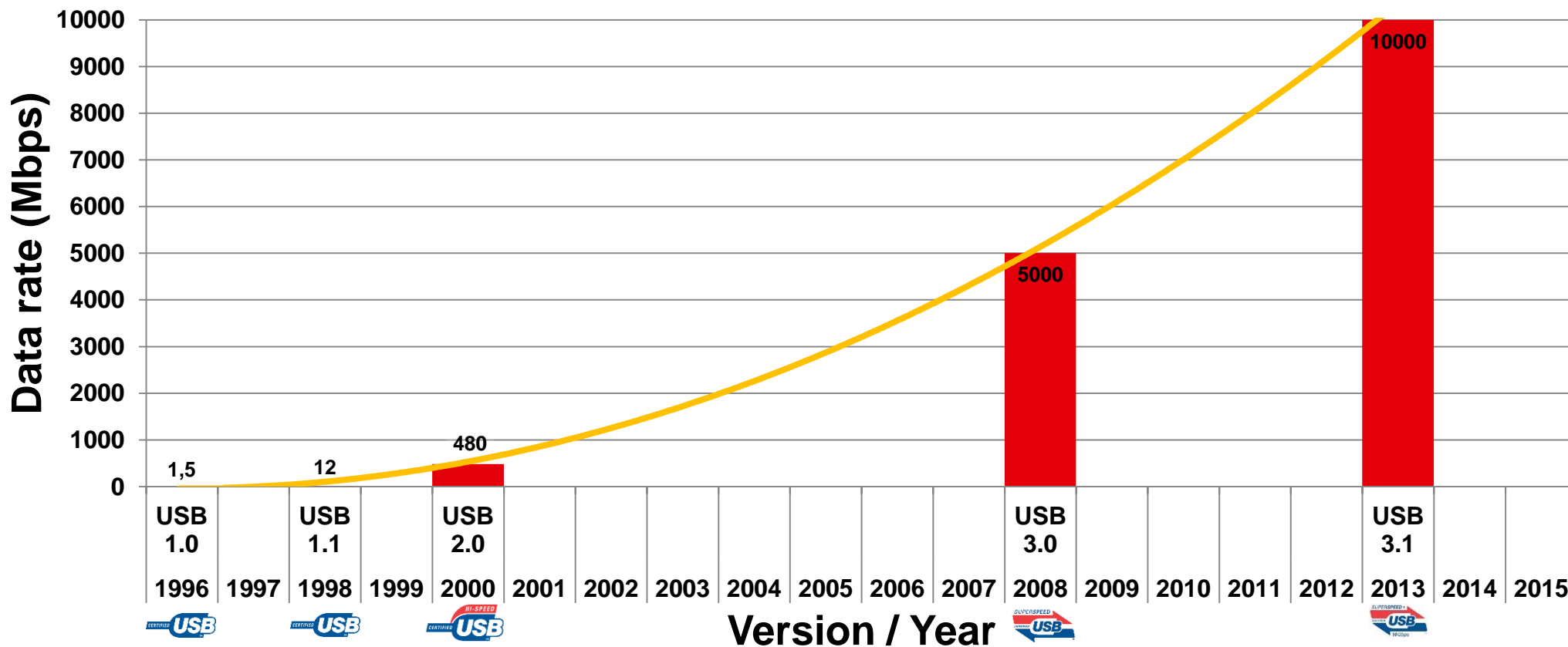
- Higher durability
- Higher data rate
- Higher current capability (Power supply)
- Reversibility feature
- Short Type (for integrated applications)





A little bit of history – USB Versions?

➤ USB = Universal Serial Bus



USB Overview - USB Versions

➤ USB 1.x – January 1996

- Low-speed: 1.5Mbps
- Full-speed: 12 Mbps

➤ USB 1.1 – July 1998

➤ USB 2.0 – April 2000

- Full backwards compatibility with USB 1.1
- Adds high-speed: 480 Mbps

➤ USB 3.0 – December 2008

- Super-speed: 5 Gbps
- Backwards-compatible to USB 2.0 standard

➤ USB 3.1 – August 2013

- Super-speed +: 10 Gbps
- Backwards-compatible to USB 3.0 standard



A little bit of history – From 2.0...



Year/Version | USB 2.0 – 2000

➤ A



➤ B



➤ Mini



➤ Micro



➤ Data rate

480 Mbps

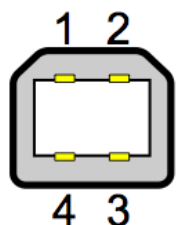
➤ Power

500mA / 5V

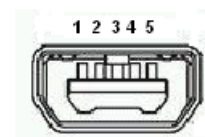


USB 2.0 Overview – Mini & Micro Types

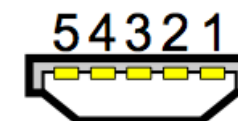
- 5 contacts on Mini and Micro types
- 4 contacts on “Standard” types



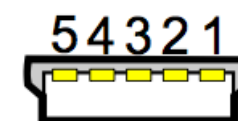
➤ **WHY?**



Mini-AB



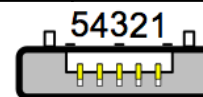
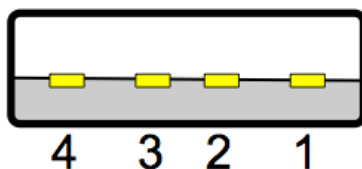
Mini-A



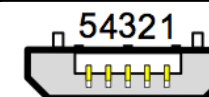
Mini-B

Contact No.	Signal Name	Description
1	VBUS	Power
2	Data-	USB 2.0 Twisted pair
3	Data+	
4	GND	Ground for power return
Shell	Shield	

Contact No.	Signal Name	Description
1	VBUS	Power
2	Data-	USB 2.0 Twisted pair
3	Data+	
4	ID	OTG identification
5	GND	Ground for power return
Shell	Shield	



Micro-A



Micro-B

- Cable A to Micro/Mini: loose of 1 wire – information

A little bit of history – ...to USB 3.0 ...



Year/Version	USB 2.0 – 2000	USB 3.0 – 2008
➤ A		
➤ B		
➤ Mini		
➤ Micro		
➤ Data rate	480 Mbps	5000 Mbps
➤ Power	500mA / 5V	900mA / 5V

USB 3.0 Overview - History / Benchmark

- Based on Microsoft tests: (showed at WinHEC 2008 on Nov 6)

Transfer of a 25GB Blu-ray movie:

USB 1.1: 9.3 hours

USB 2.0: 13.9 minutes

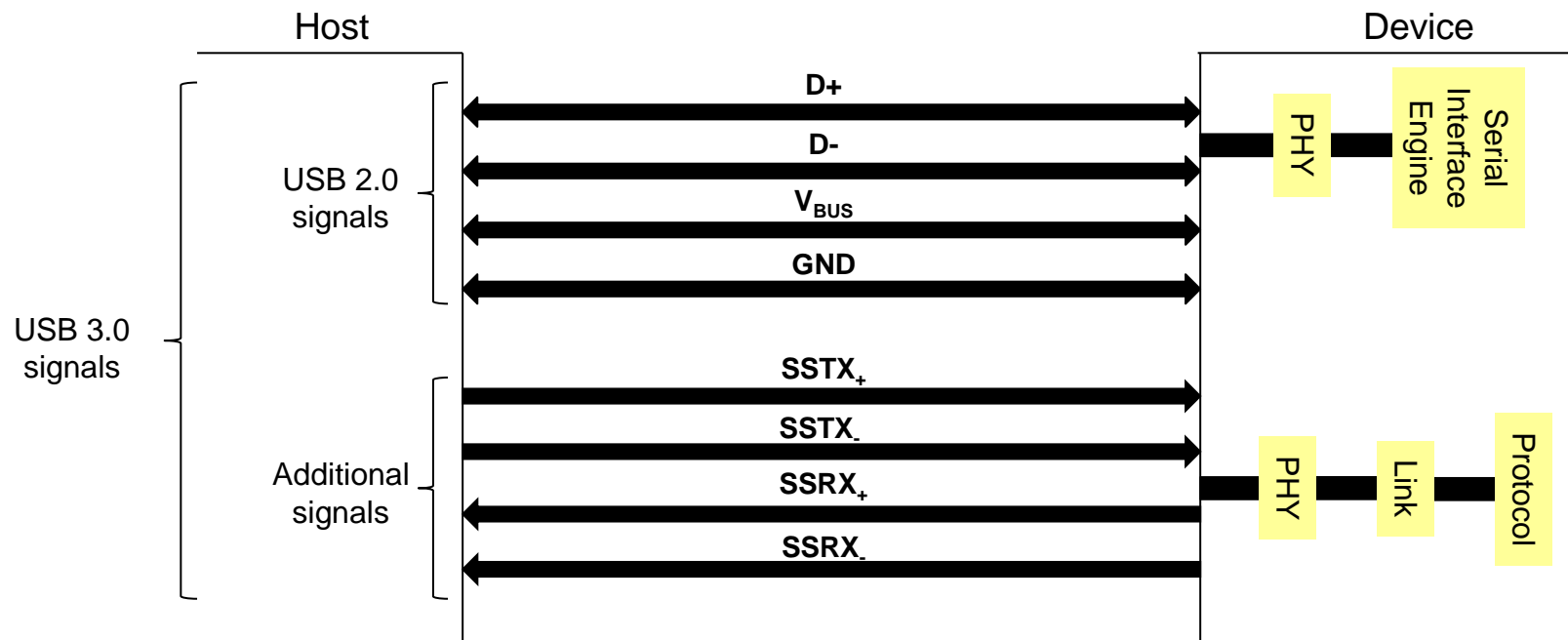
USB 3.0: 70 seconds

≈ x 40

≈ x 12

USB version	Data rate
USB 1.0	1,5 Mbps
USB 1.1	12 Mbps
USB 2.0	480 Mbps
USB 3.0	5 Gbps

USB 3.0 Overview - Architecture and protocol



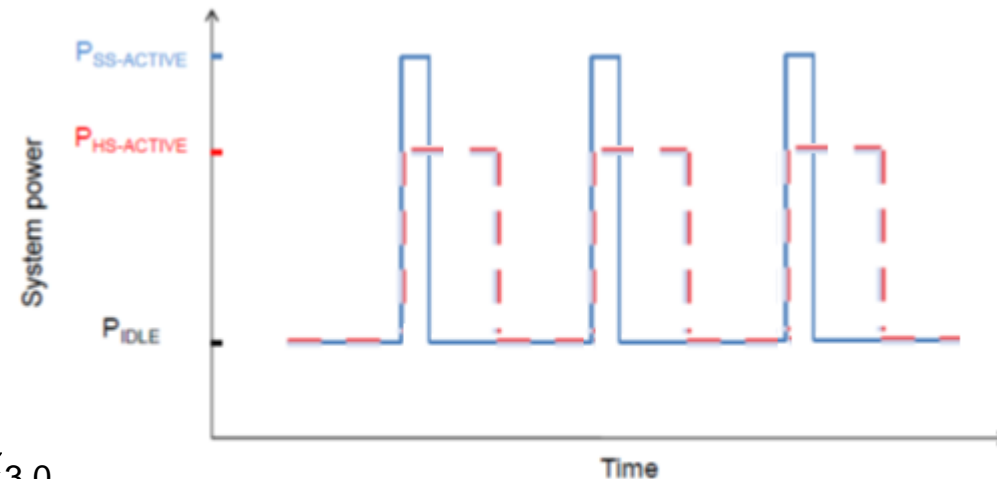
Note: Tx & Rx are defined from the host perspective

USB 3.0 Overview – Power Management

With up to 150 mA per unit (+50 % compared to USB 2.0) and up to 6 units together, USB 3.0 can carry up to:

$$900 \text{ mA} * 5\text{V} = 4,5\text{W} = P_{\text{SS_ACTIVE}} \quad \text{Vs.} \quad 500 \text{ mA} * 5\text{V} = 2,5\text{W} = P_{\text{HS_ACTIVE}}$$

This means a total **80% increase** compared to USB 2.0.



$$P_{\text{TOTAL}} = P_{\text{IDLE}} + (P_{\text{ACTIVE}} - P_{\text{IDLE}}) * \alpha$$

$$P_{\text{TOTAL3}} = P_{\text{IDLE}} + 1,8 * (P_{\text{HS_ACTIVE}} - P_{\text{IDLE}}) * \alpha_{3.0}$$

$$P_{\text{TOTAL2}} = P_{\text{IDLE}} + (P_{\text{HS_ACTIVE}} - P_{\text{IDLE}}) * \alpha_{2.0}$$

P_{IDLE} : system power when no data transfer is taking place
 $P_{\text{HS_ACTIVE}}$: system power in High Speed (2.0) mode
 $P_{\text{SS_ACTIVE}}$: system power in Super Speed (3.0) mode

A little bit of history – ...to USB 3.1 !!!



Year/Version

USB 2.0 – 2000

USB 3.0 – 2008

USB 3.1 – 2013

➤ A



➤ B



➤ Mini



➤ Micro



➤ **C**



➤ Data rate

480 Mbps

5000 Mbps

10000 Mbps

➤ Power

500mA / 5V

900mA / 5V

5A / 5V

Specification, Requirements & Performances

Electrical



- Contact resistance
 - V_{BUS} & GND Pins : 30m Ω max
 - Other Pins: 50m Ω max
 - $\Delta_{CONTACT RESISTANCE}$: 10m Ω max after mating cycles
- Insulation resistance > 100M Ω
- Dielectric Withstanding Voltage > 100M Ω
- Contact Current & Voltage rating:

Type	A		B		Micro B		C		
	Power Pins	Other Pins	Power Pins	Other Pins	Power Pins	Other Pins	Power Pins		Other Pins
Pin Number	1 & 4	-	1 & 4	-	1 & 5	-	A1,A4,A9 & A12 B1,B4,B9 & B12	A5 & B5	-
Current	1.8 A	0.25 A	1.8 A	0.25 A	1.8 A	0.25 A	1.5 / 5 A	1.25 A	0.25 A
Voltage	5 V								

Specification, Requirements & Performances

Mechanical



➤ Durability – Mating cycles

	A	B	Micro B	C
Mating cycles	1500 or 5000		10000	
Speed	200 cycles / hour			

➤ Insertion force

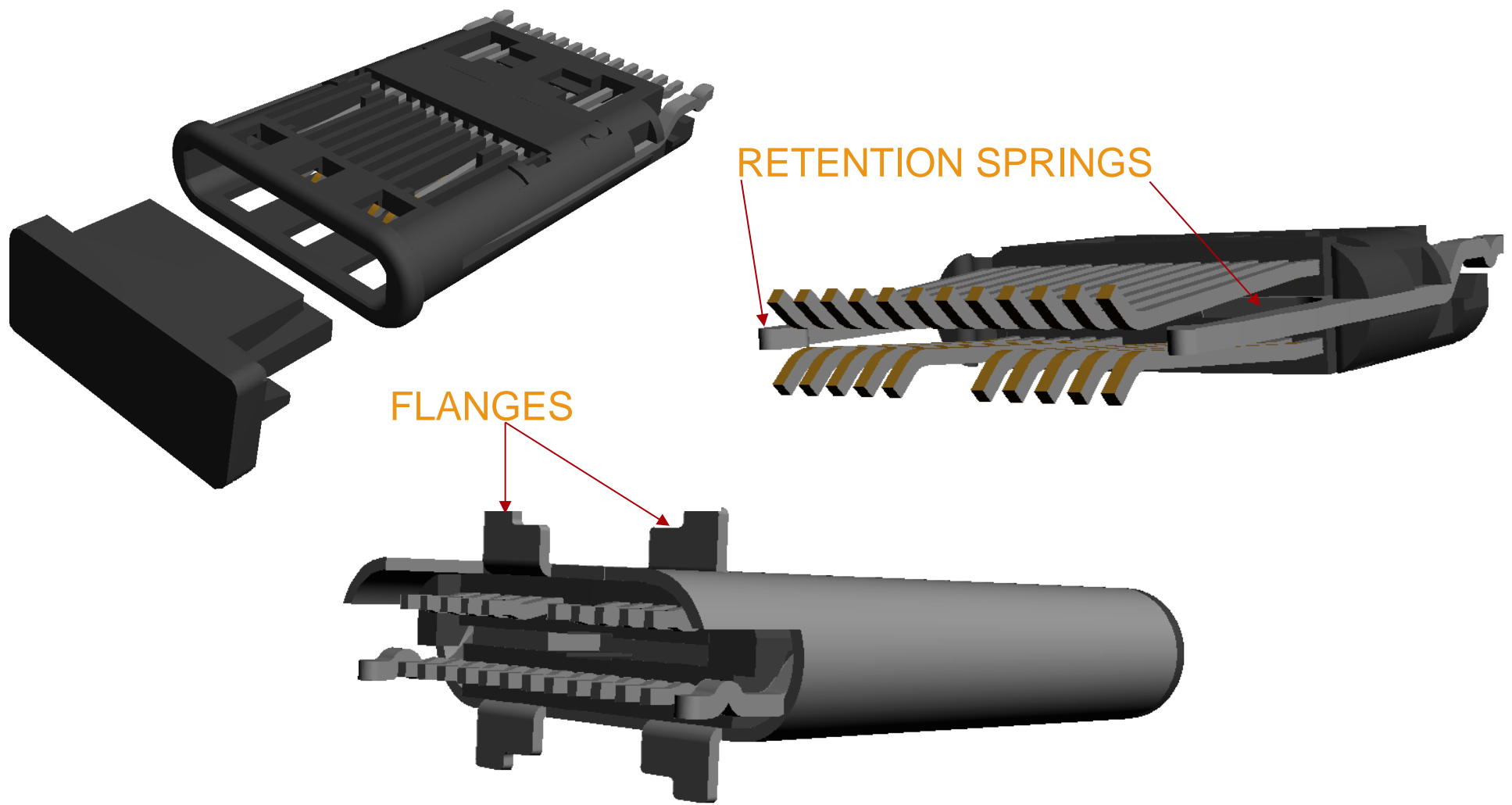
	A	B	Micro B	C
Insertion force	< 35 N	< 35 N	< 35 N	5 N to 8 N
Speed	12.5 mm / min			

➤ Extraction force (retention)

	A	B	Micro B	C
Standard mating cycles	1500	1500	10000	10000
Before mating cycles	> 10 N	> 10 N	10 N < Force < 25 N	8 N < Force < 20 N
After 1000 cycles	-	-	-	6 N < Force < 20 N
At max. cycles	> 8 N	> 8 N	8 N < Force < 25 N	6 N < Force < 20 N
Speed	12.5 mm / min			

USB 3.1 Product Overview

Type C Plug Design – 632 712 000 011



Type C Receptacles

- **Order code:**

632 723 X00 011

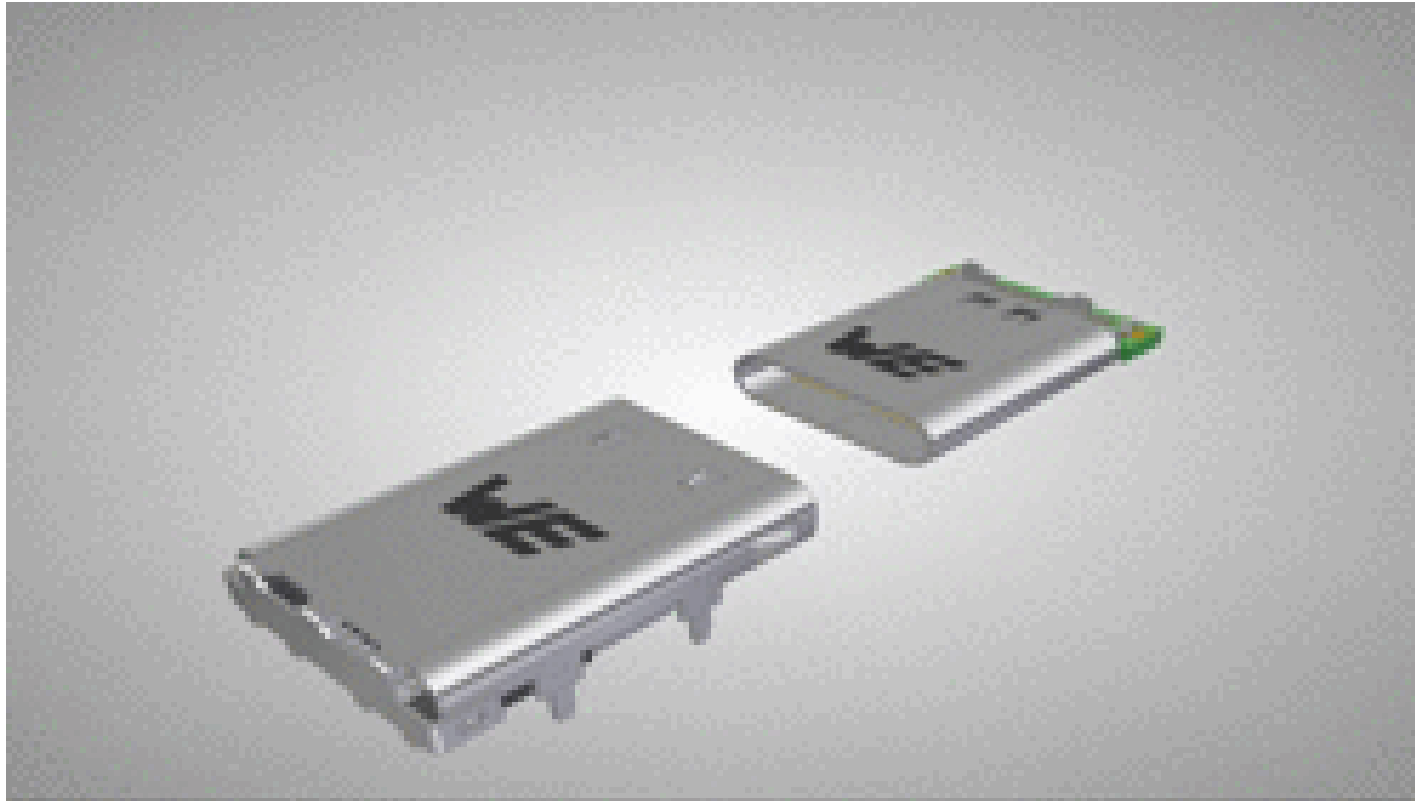
- **Product features:**

1. Material: LCP; black
2. Rated Current: 5 A
3. Rated Voltage: 5 VDC (12VDC/20VDC)
4. Durability: 10 000 cycles
5. Soldering: JEDEC lead free wave and reflow soldering



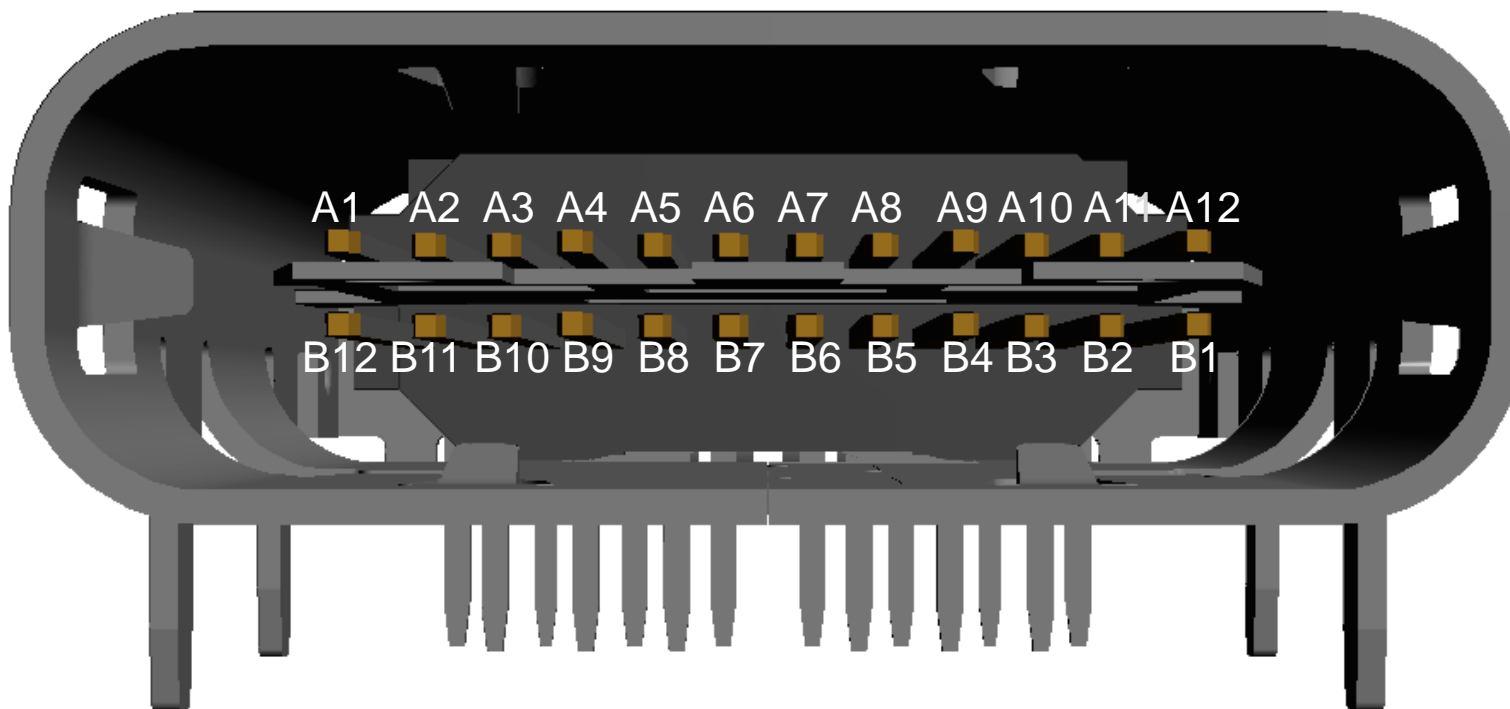
X	PCB Thickness	Pin length
1	1.00 mm	1.50 mm
3	1.60 mm	1.90 mm

Type C Receptacles – 632 723 x00 011





Type C Receptacles – 632 723 x00 011

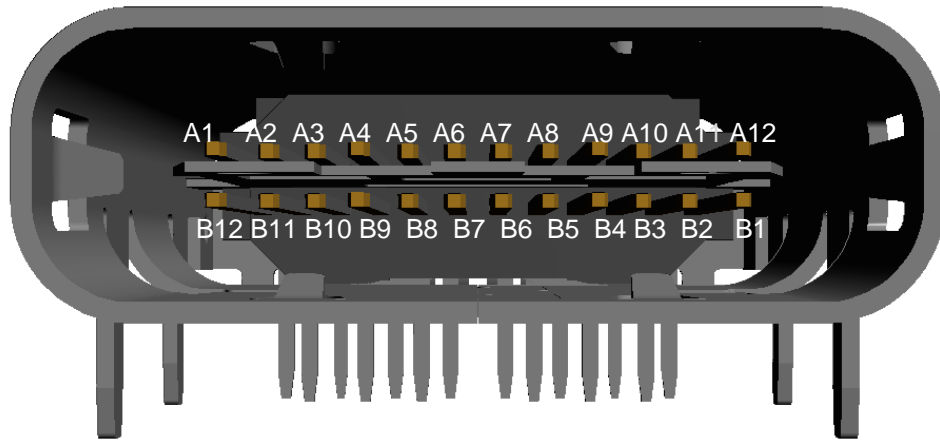


- USB 2.0
- USB 3.0
- USB 3.1

A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
GND	TX1+	TX1-	V _{BUS}	CC1	D+	D-	SBU1	V _{BUS}	RX2-	RX2+	GND
GND	RX1+	RX1-	V _{BUS}	SBU2	D-	D+	CC2	V _{BUS}	TX2-	TX2+	GND
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1



Type C Receptacles – 632 723 x00 011

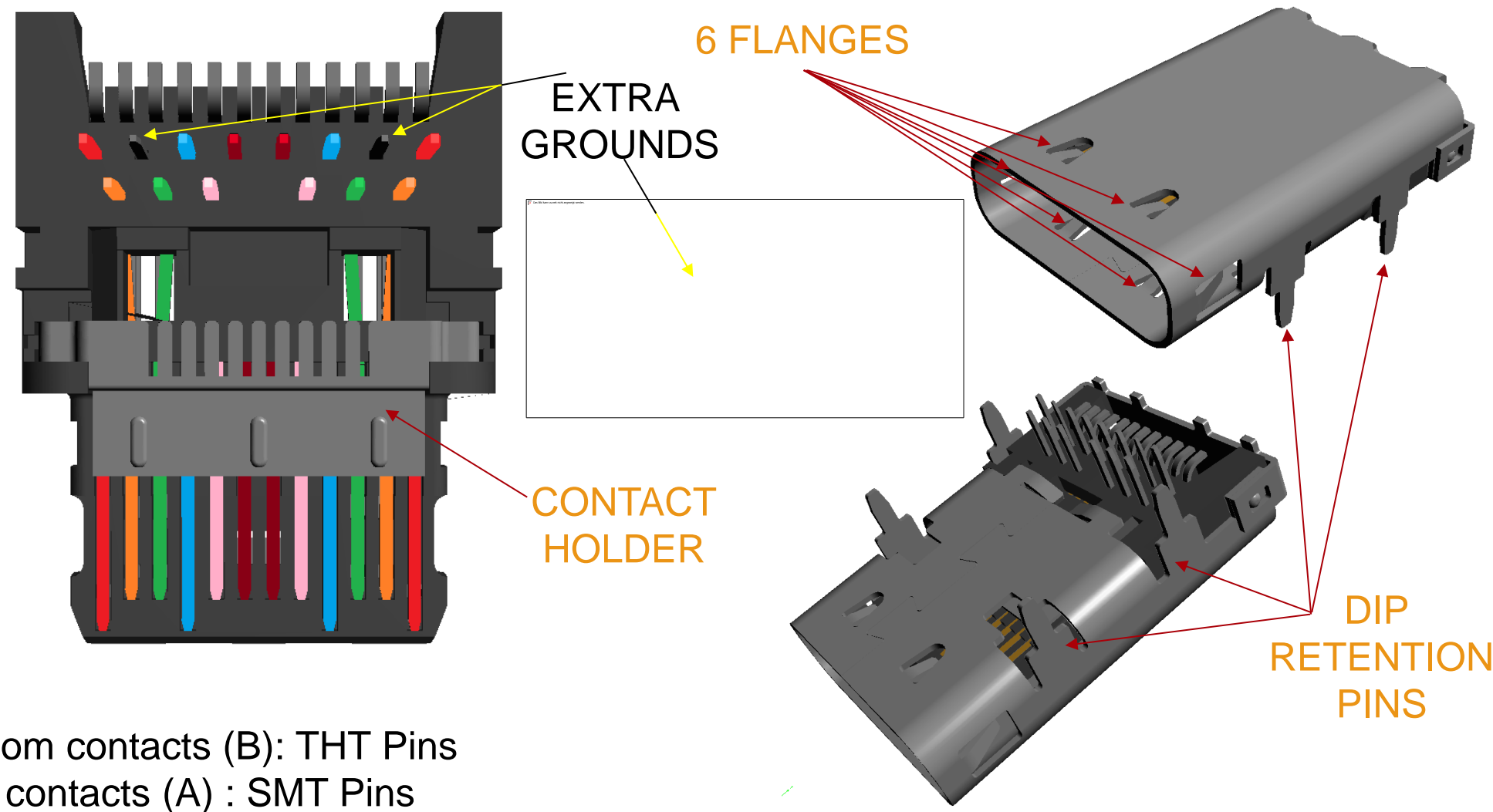


- GND** : All pins (4) are connected together
- V_{BUS}**: All pins (4) are connected together
- D** : USB 2.0 Data pair
- TX** : 2 transmission pairs
- RX**: 2 reception pairs
- CC** : Configuration Channel : Detection & Power Management + HTD Management
- SBU**: Side Band use : Alternate modes (other standards)

A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
GND	TX1+	TX1-	V _{BUS}	CC1	D+	D-	SBU1	V _{BUS}	RX2-	RX2+	GND
GND	RX1+	RX1-	V _{BUS}	SBU2	D-	D+	CC2	V _{BUS}	TX2-	TX2+	GND
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1

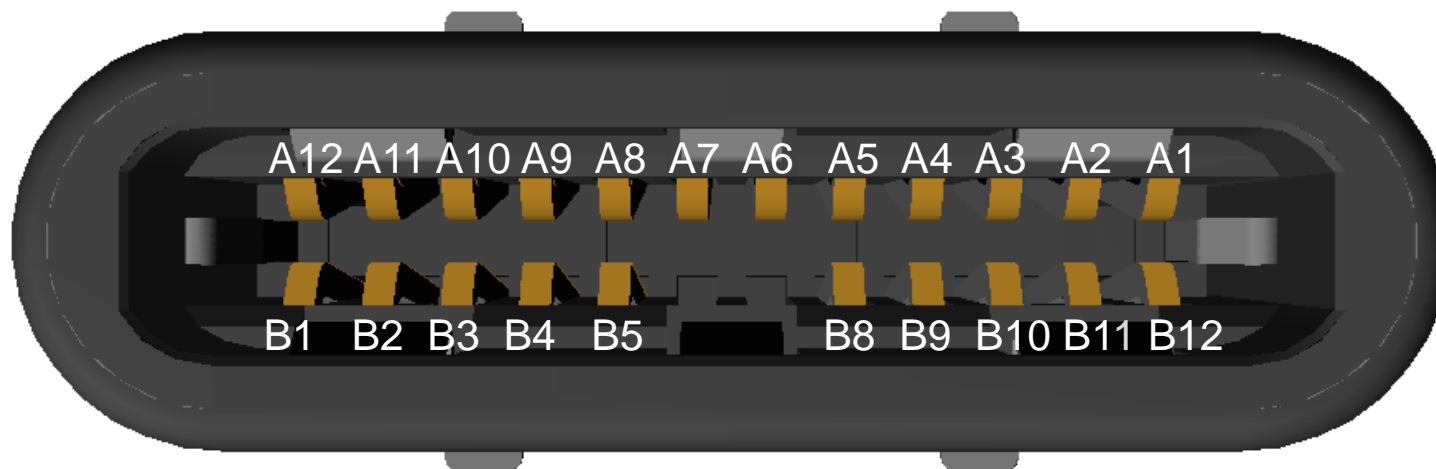
USB 3.1 Product Overview

Type C Receptacles Design – 632 723 x00 011





Type C Plug – 632 712 000 011



- USB 2.0
- USB 3.0
- USB 3.1

A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1
GND	RX2+	RX2-	V _{BUS}	SBU1	D+	D-	CC1	V _{BUS}	TX1-	TX1+	GND
GND	TX2+	TX2-	V _{BUS}	CC2			SBU2	V _{BUS}	RX1-	RX1+	GND
B1	B2	B3	B4	B5			B8	B9	B10	B11	B12

USB 3.1 Product Overview

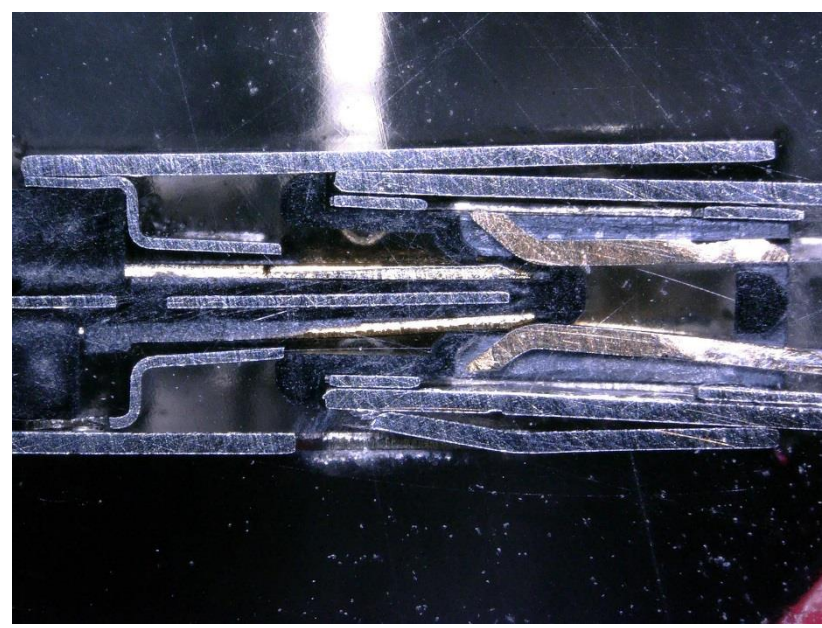
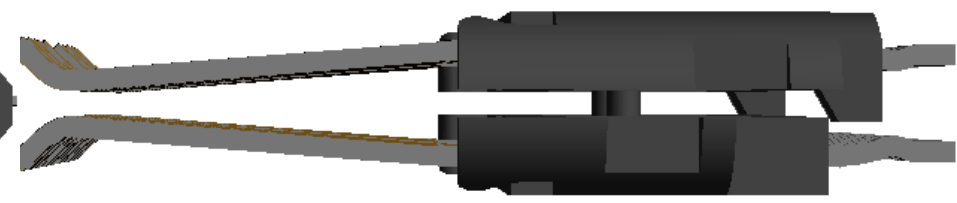
Type C Plug Design – 632 712 000 011



Receptacle – Side crossed view



Plug – Side crossed view

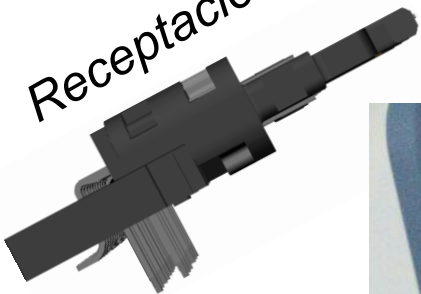


Specification, Requirements & Performances

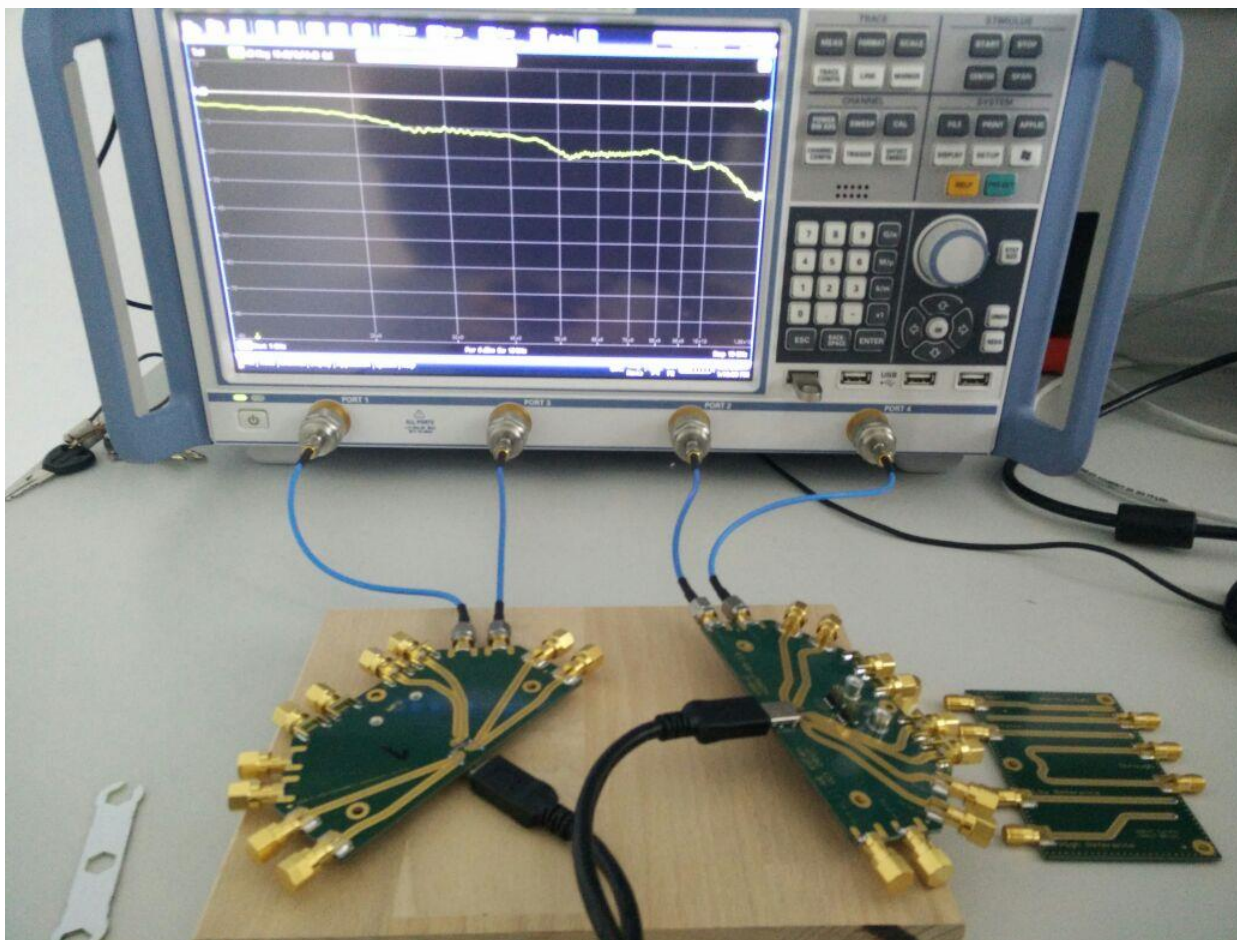
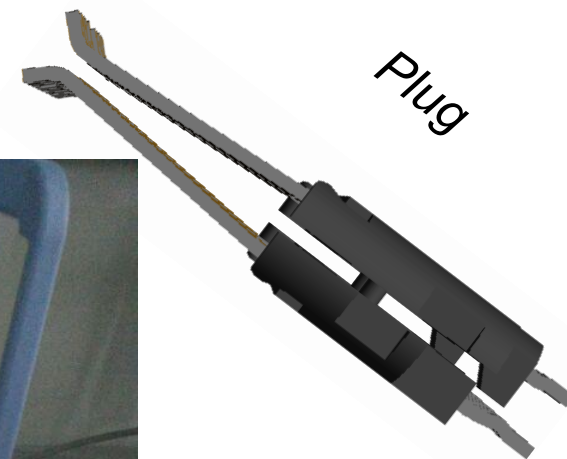
RF behavior



Receptacle

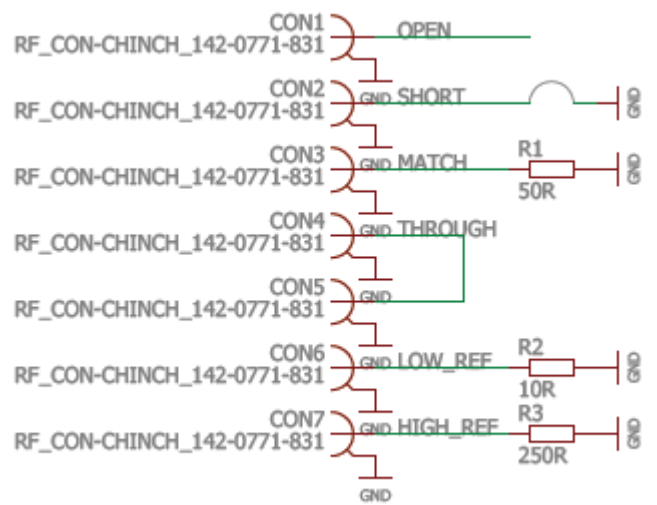


Plug

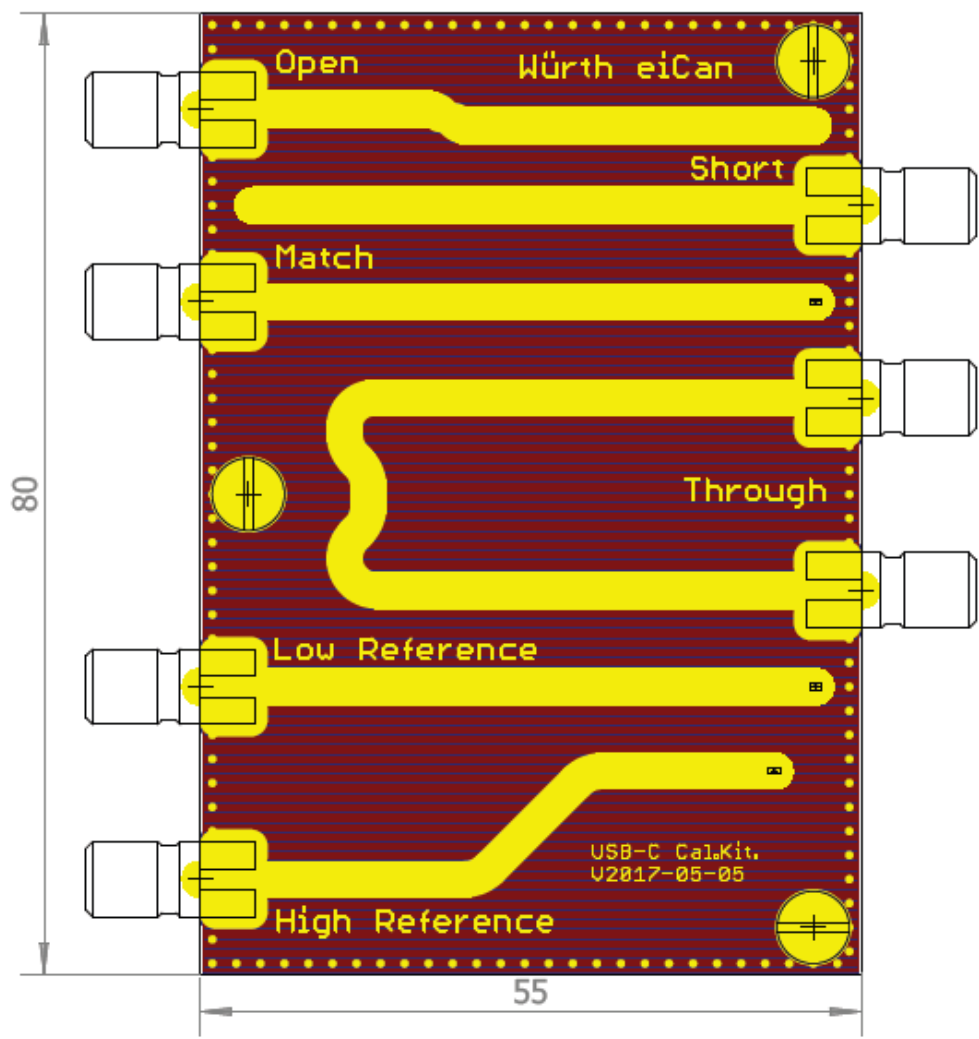


Specification, Requirements & Performances

RF behavior

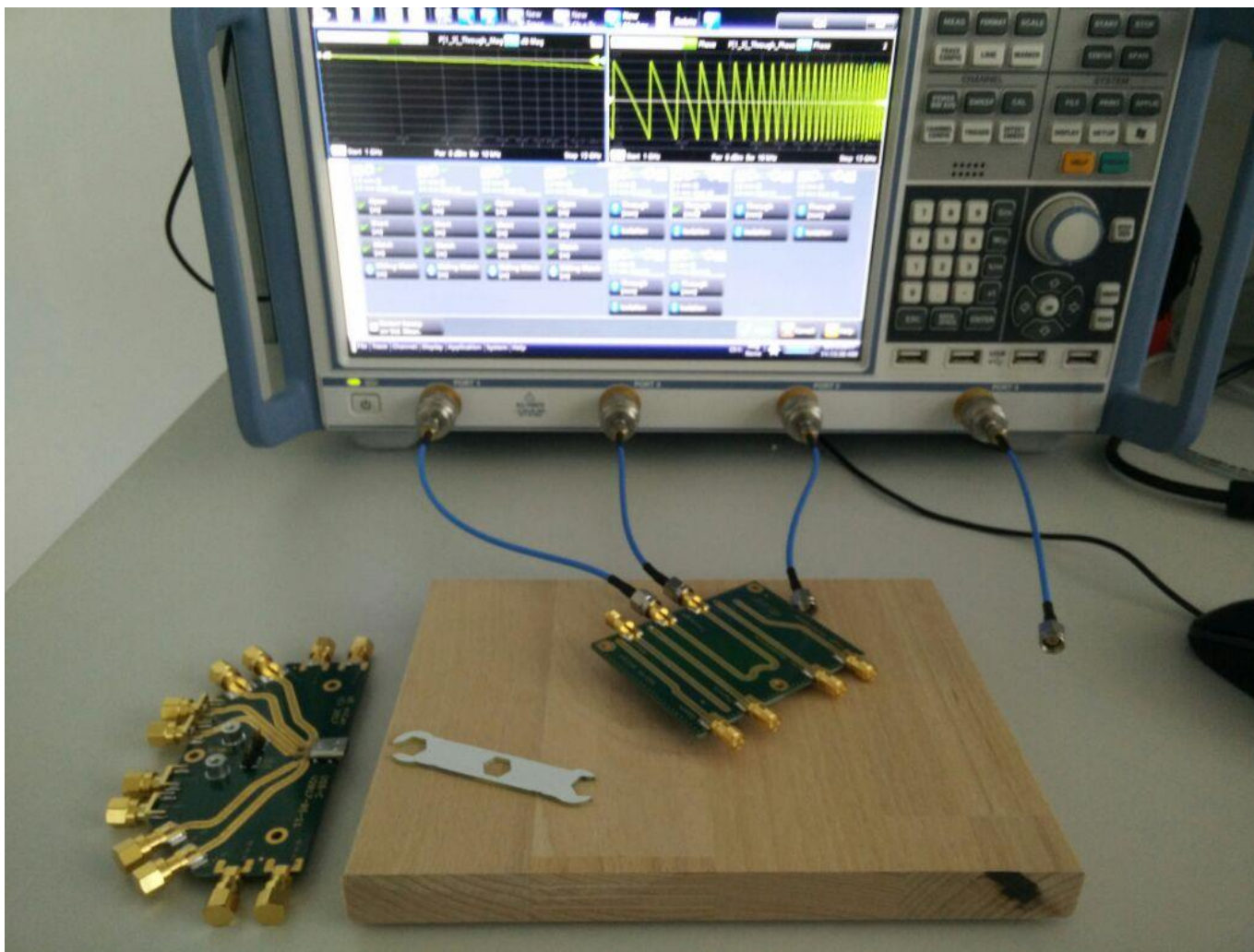


Calibration board



Specification, Requirements & Performances

RF behavior



Calibration board

Specification, Requirements & Performances

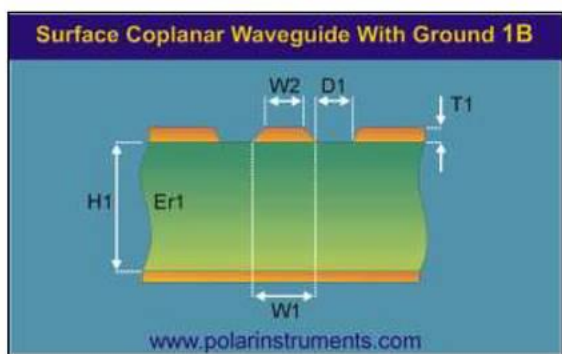
RF behavior



Calibration board

The microstrip conductor has to be like Würth Elektronik suggests.

Polar Si8000 Controlled Impedance Quick Solver



			Toleranz	Minimum	Maximum
Substrat 1 Dicke	H1	322,0000 +/-	0,0000	322,0000	322,0000
Substrat 1 Dielektrikum	Er1	4,6000 +/-	0,0000	4,6000	4,6000
Untere Leiterbreite	W1	450,0000 +/-	0,0000	450,0000	450,0000
Obere Leiterbreite	W2	420,0000 +/-	0,0000	420,0000	420,0000
Separation Massestreifen	D1	225,0000 +/-	0,0000	225,0000	225,0000
Leiterbahndicke	T1	50,0000 +/-	0,0000	50,0000	50,0000
<hr/>					
Impedanz	Zo	50,13	-----	0,00	0,00
Laufzeit (ps/m)	D	5725,350	-----	0,000	0,000
Induktivität (nH/m)	L	287,010	-----	0,000	0,000
Kapazität (pF/m)	C	114,211	-----	0,000	0,000

Specification, Requirements & Performances

RF behavior



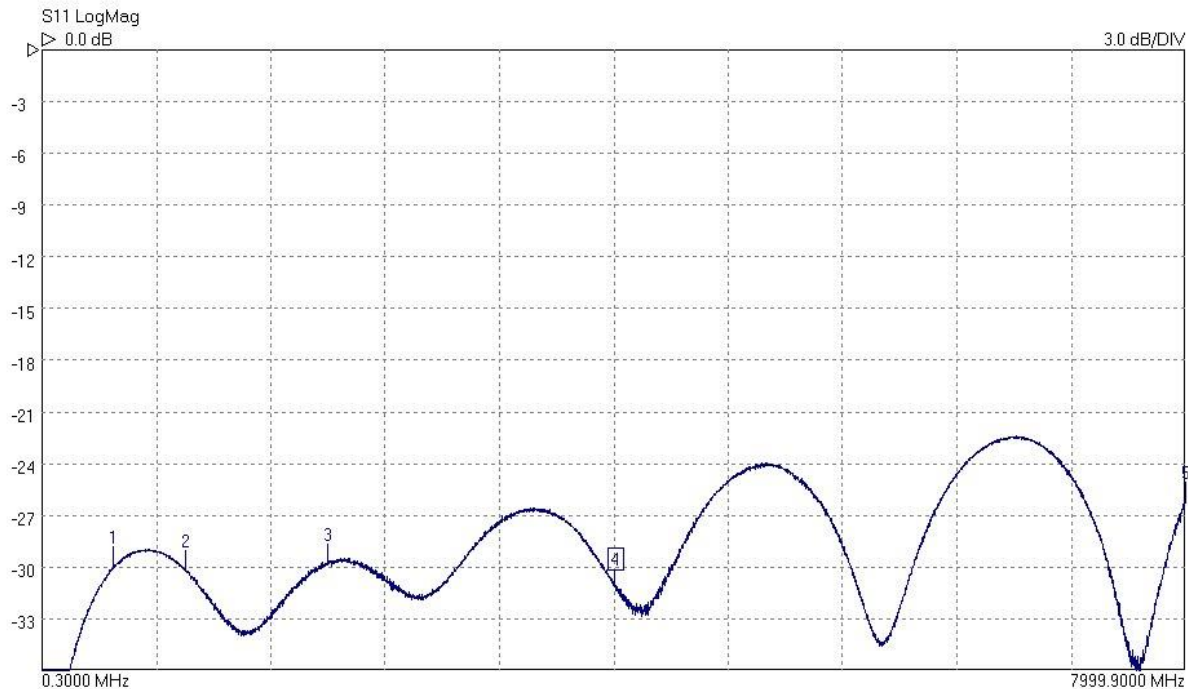
Specification, Requirements & Performances

RF behavior



Calibrationboard

The adjustment of the line:



MARKERS

Graph 1 S11
Ref Plane 8.50 mm

- Marker 1**
500.2750 MHz
-29.922 dB
- Marker 2**
1000.2500 MHz
-30.131 dB
- Marker 3**
2000.2000 MHz
-29.794 dB
- Marker 4**
4000.1000 MHz
-31.142 dB
- Marker 5**
7999.9000 MHz
-26.158 dB

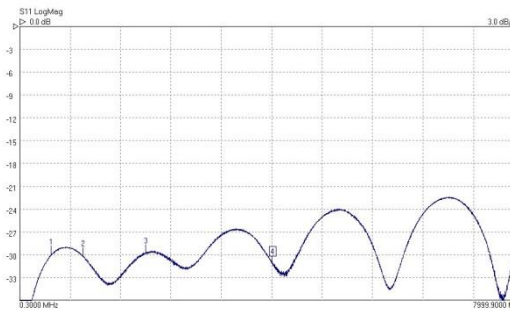
Specification, Requirements & Performances

RF behavior

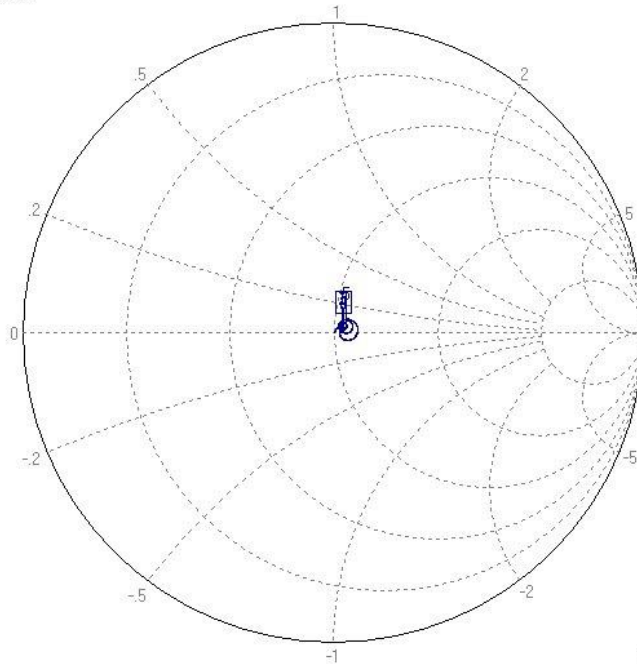


Calibrationboard

The adjustment of the line:



S11 Reflection Z



0.3000 MHz

7999.9000 MHz

MARKERS

Graph 1 S11	
Ref Plane 8.50 mm	
Marker 1	500.2750 MHz 52.438, 2.179 j, 693.597pH
Marker 2	1000.2500 MHz 53.147, 0.651 j, 103.610pH
Marker 3	2000.2000 MHz 52.764, 1.853 j, 147.457pH
Marker 4	4000.1000 MHz 52.684, 0.949 j, 37.759pH
Marker 5	7999.9000 MHz 53.680, 3.539 j, 70.406pH

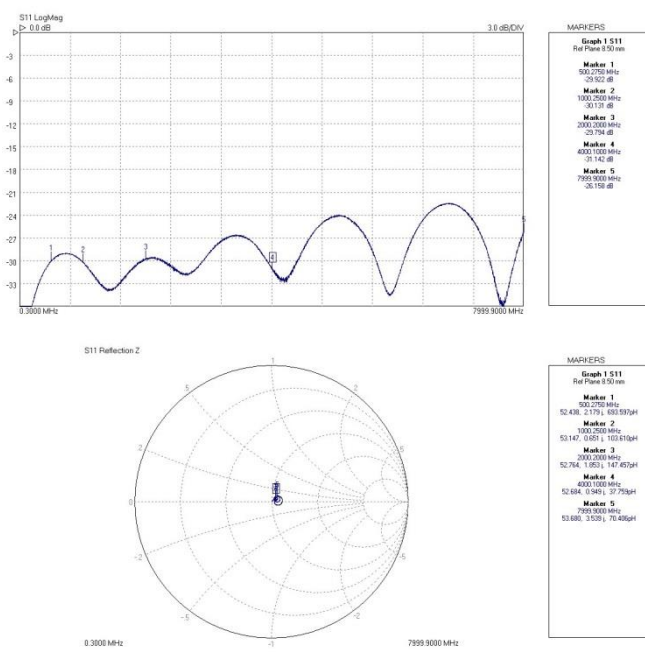
Specification, Requirements & Performances

RF behavior



Calibrationboard

The adjustment of the line:



This corresponds to a line impedance of approximately 53 Ω.

Specification, Requirements & Performances

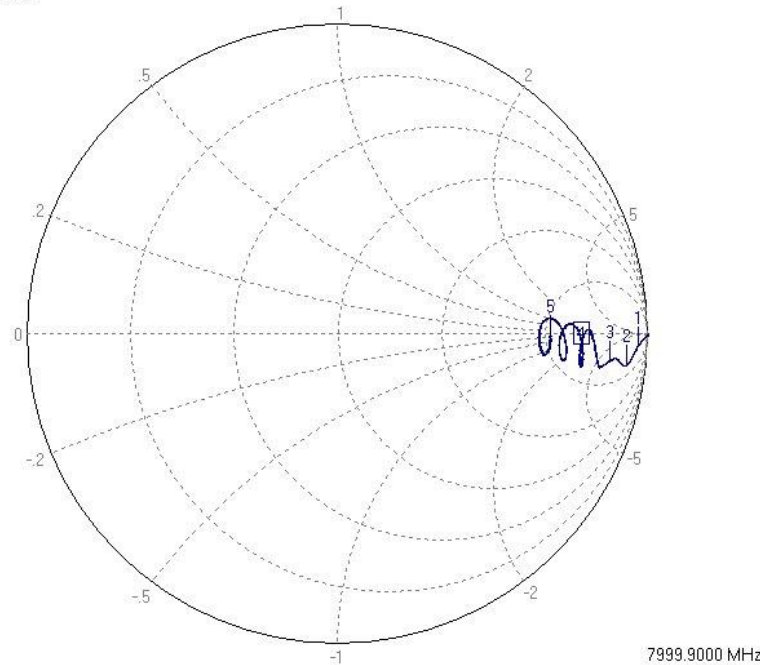
RF behavior



Calibrationboard

Line length: smith open = 100mm
(electrical)

S11 Reflection Z



MARKERS

Graph 1 S11	
Ref Plane 100.00 mm	
Marker 1	500.2750 MHz 1133.024, -1341.760 j, 0.237pF
Marker 2	1000.2500 MHz 421.432, -665.504 j, 0.239pF
Marker 3	2000.2000 MHz 478.002, -367.583 j, 0.216pF
Marker 4	4000.1000 MHz 336.289, -153.940 j, 0.258pF
Marker 5	7999.9000 MHz 263.925, -4.054 j, 4.907pF

Specification, Requirements & Performances

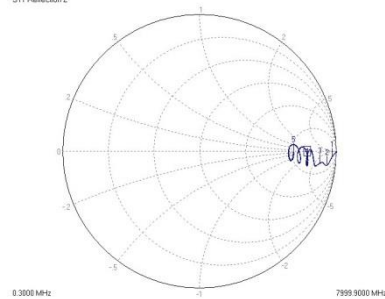
RF behavior



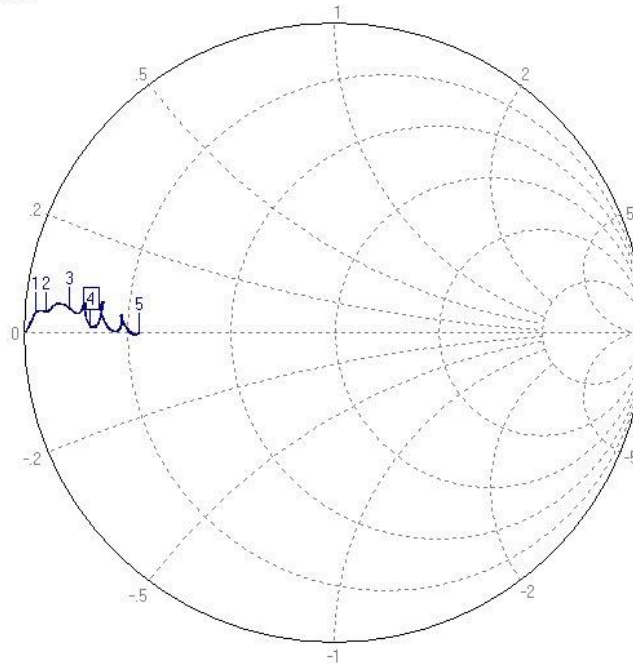
Calibrationboard

Line length: smith short = 99,79mm (electrical)

S11 Reflection Z



S11 Reflection Z



MARKERS

Graph 1 S11	
Ref Plane 99.79 mm	
Marker 1	500.2750 MHz 0.882, 1.701 j, 541.445pH
Marker 2	1000.2500 MHz 1.729, 1.819 j, 289.503pH
Marker 3	2000.2000 MHz 3.699, 2.374 j, 188.917pH
Marker 4	4000.1000 MHz 5.882, 0.677 j, 26.937pH
Marker 5	7999.9000 MHz 11.269, 0.014 j, 0.279pH

Specification, Requirements & Performances

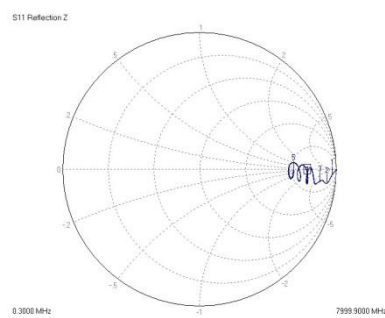
RF behavior



Calibrationboard

With an SMA plug length of 8.5mm this gives an electrical length of 91.4mm.

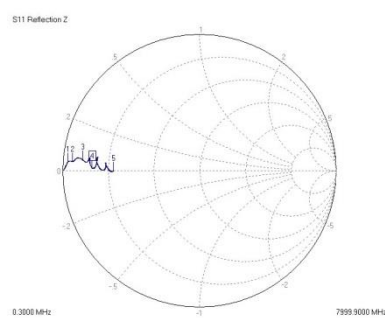
With a mechanical length of 51.0 mm, this results in a shortening factor of 0.558 and thus a running time of 5977ps / m (compared to 5725ps / m).



MARKERS

Graph 1 S11
Ref Plane: 100.00mm

Marker 1	500.2725 MHz	1133.024	1.741	160	8.220pF
Marker 2	1000.5450 MHz	421.432	465.504	0.228pF	
Marker 3	2000.1090 MHz	470.002	207.923	0.211pF	
Marker 4	4000.2180 MHz	336.286	155.846	0.259pF	
Marker 5	7999.9360 MHz	263.525	4.054	4.907pF	



MARKERS

Graph 1 S11
Ref Plane: 93.70mm

Marker 1	500.2725 MHz	0.882	1.751	541	445pH
Marker 2	1000.5450 MHz	1.728	1.071	265.583pH	
Marker 3	2000.1090 MHz	3.689	2.254	188.917pH	
Marker 4	4000.2180 MHz	5.882	0.577	26.330pH	
Marker 5	7999.9360 MHz	11.268	0.014	0.279pH	

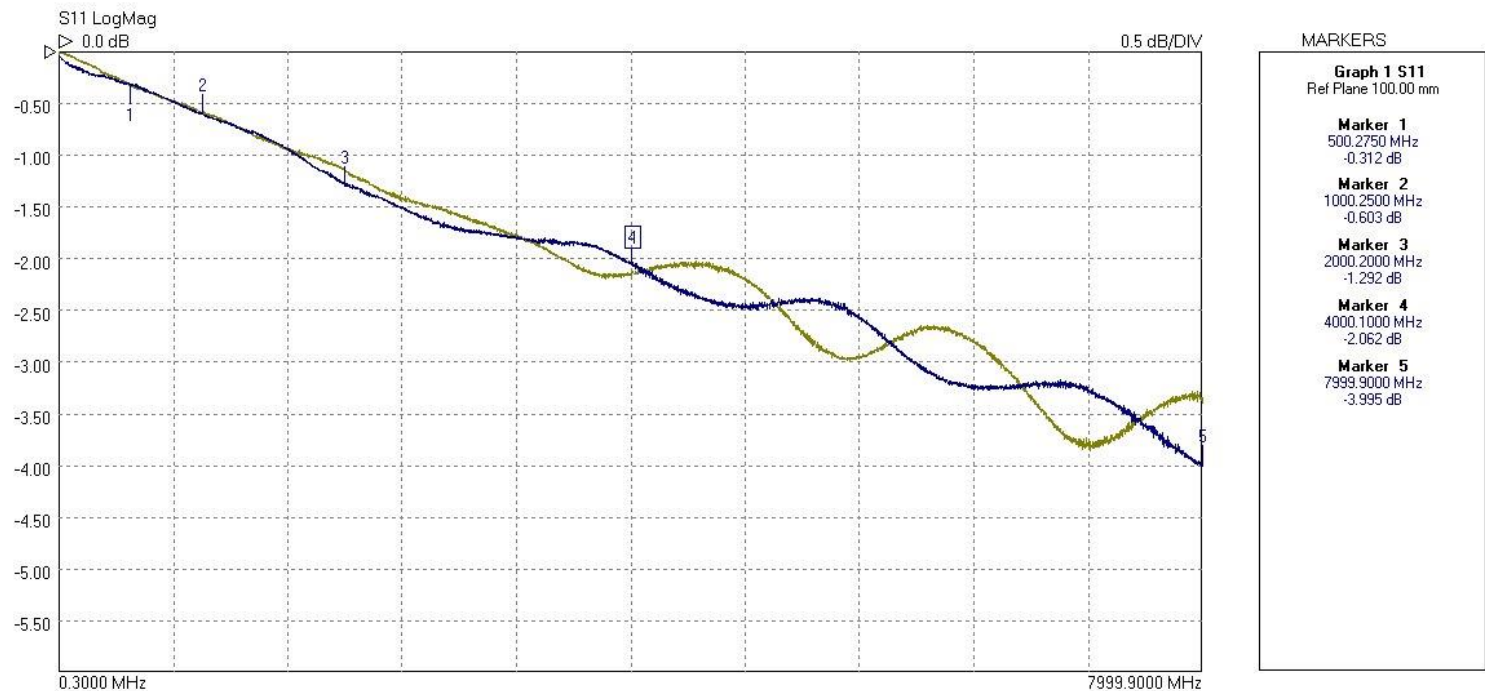
Specification, Requirements & Performances

RF behavior



Calibrationboard

Insertion loss (refelction loss open / short)



Specification, Requirements & Performances

RF behavior

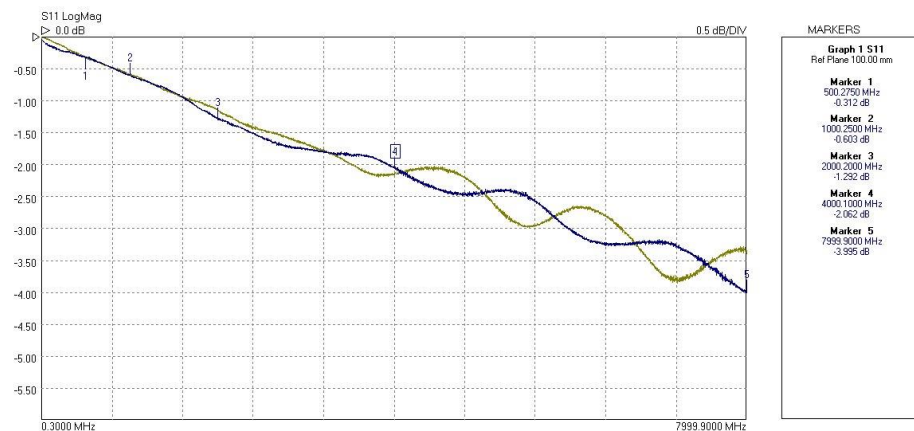


Calibrationboard

Insertion loss (reflection loss open / short)

As expected, open and short show a counter-image.

The real attenuation is half the value since the wave is attenuated on the return path.



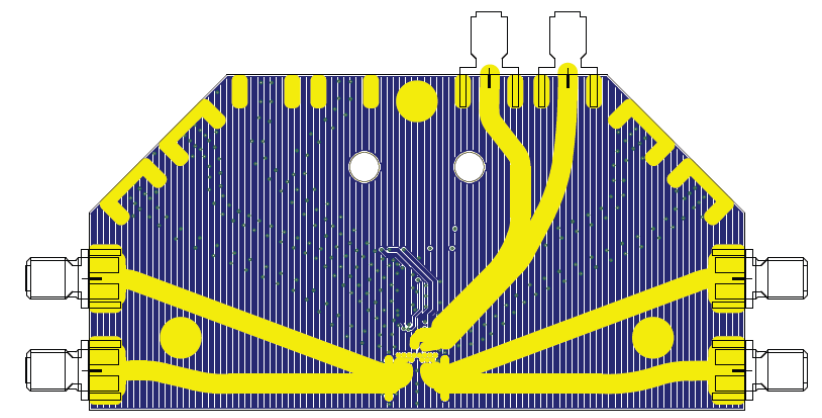
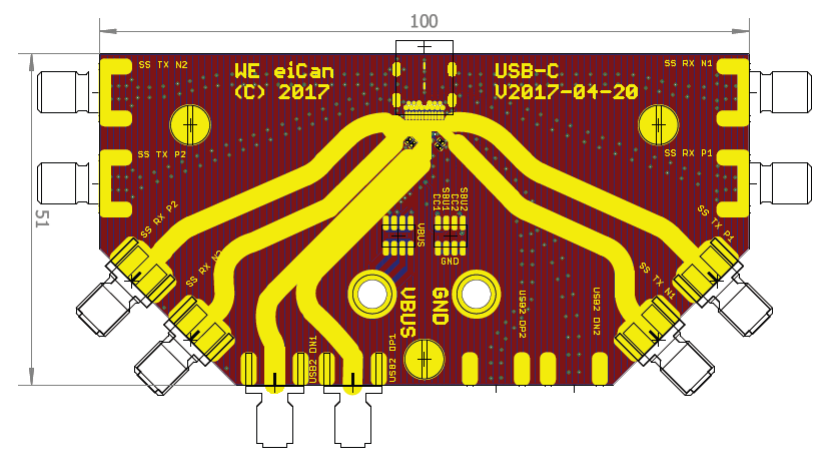
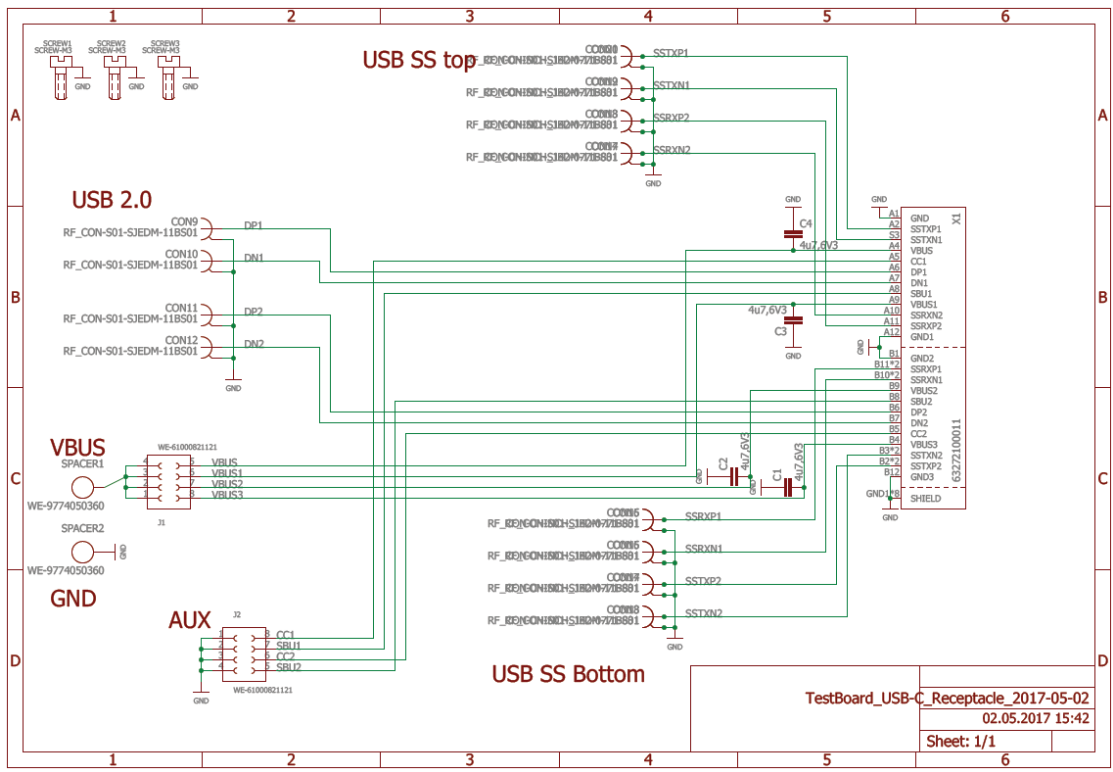
1.5 dB / m at 0.5 GHz
 3 dB / m at 1 GHz
 6 dB / m at 2 GHz
 10.5 dB / m at 4 GHz
 19 dB / m at 8 GHz

Specification, Requirements & Performances

RF behavior

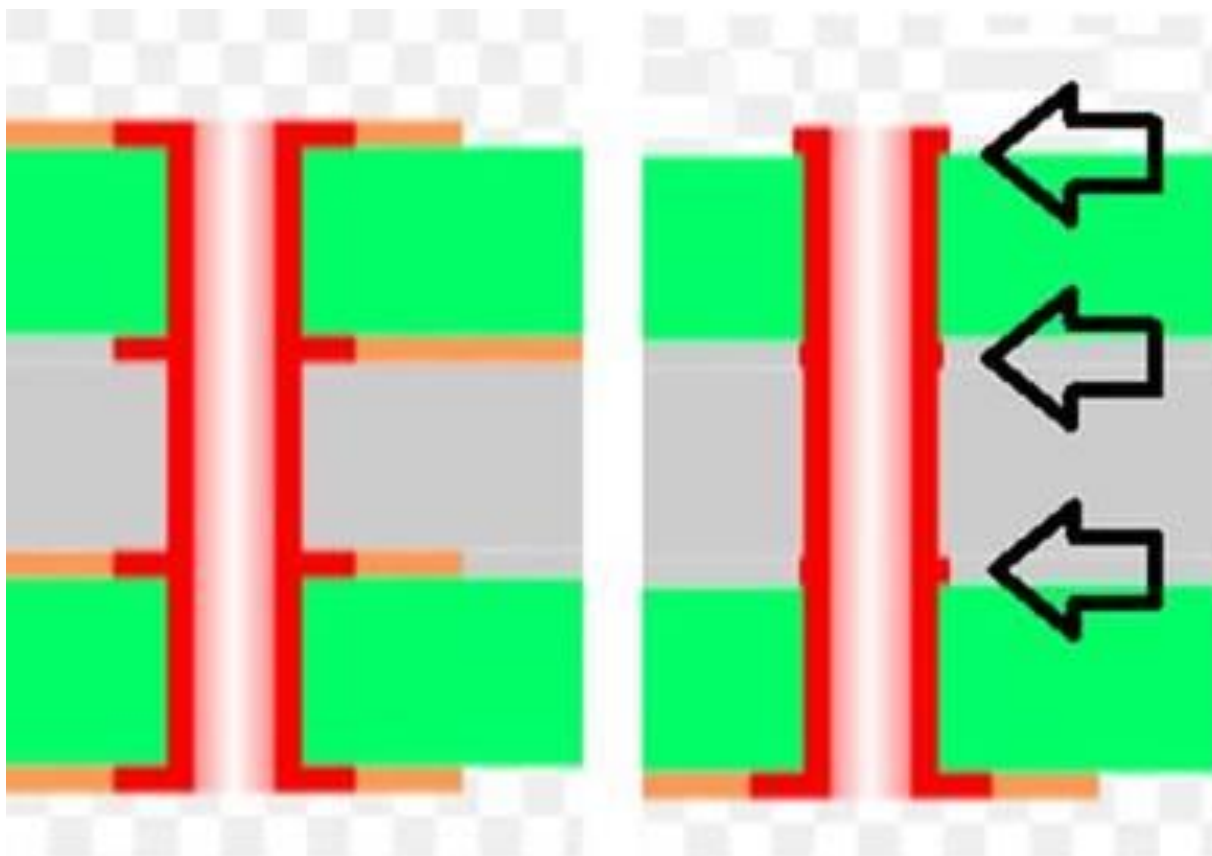


Testboard



Specification, Requirements & Performances

RF behavior



Testboard

VIA preparation:

Without rest ring is important to avoid capacitive and inductive effects between the layers.

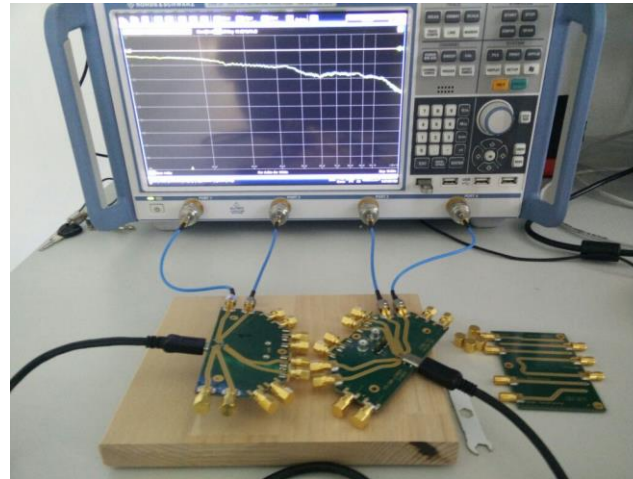
Specification, Requirements & Performances

RF behavior

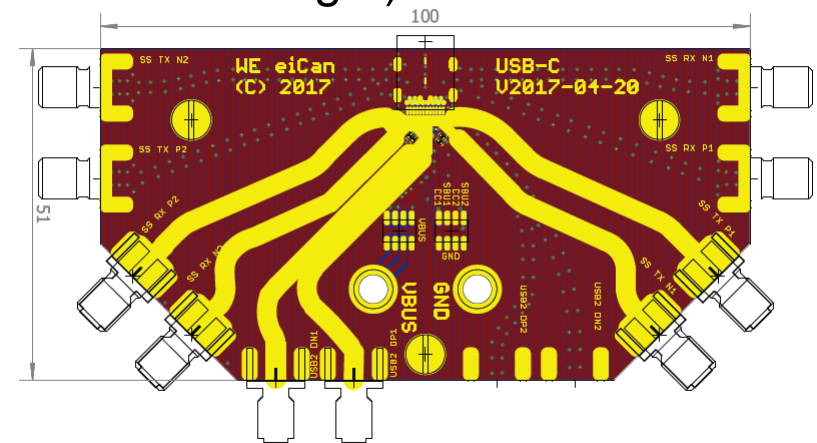
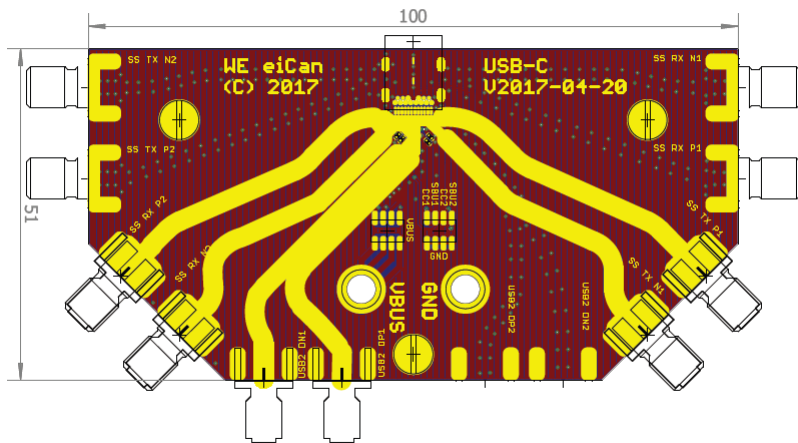
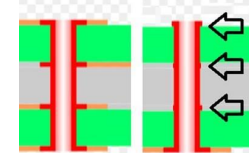
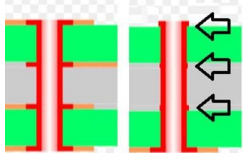


VIA
USB-C (Hybrid mount 623723300011)
USB-C Plug

VIA
USB-C (Hybrid mount 623723300011)
USB-C Plug



USB Cable (632910731731)
USB3.1 cable C Male to C Mail 100cm length)

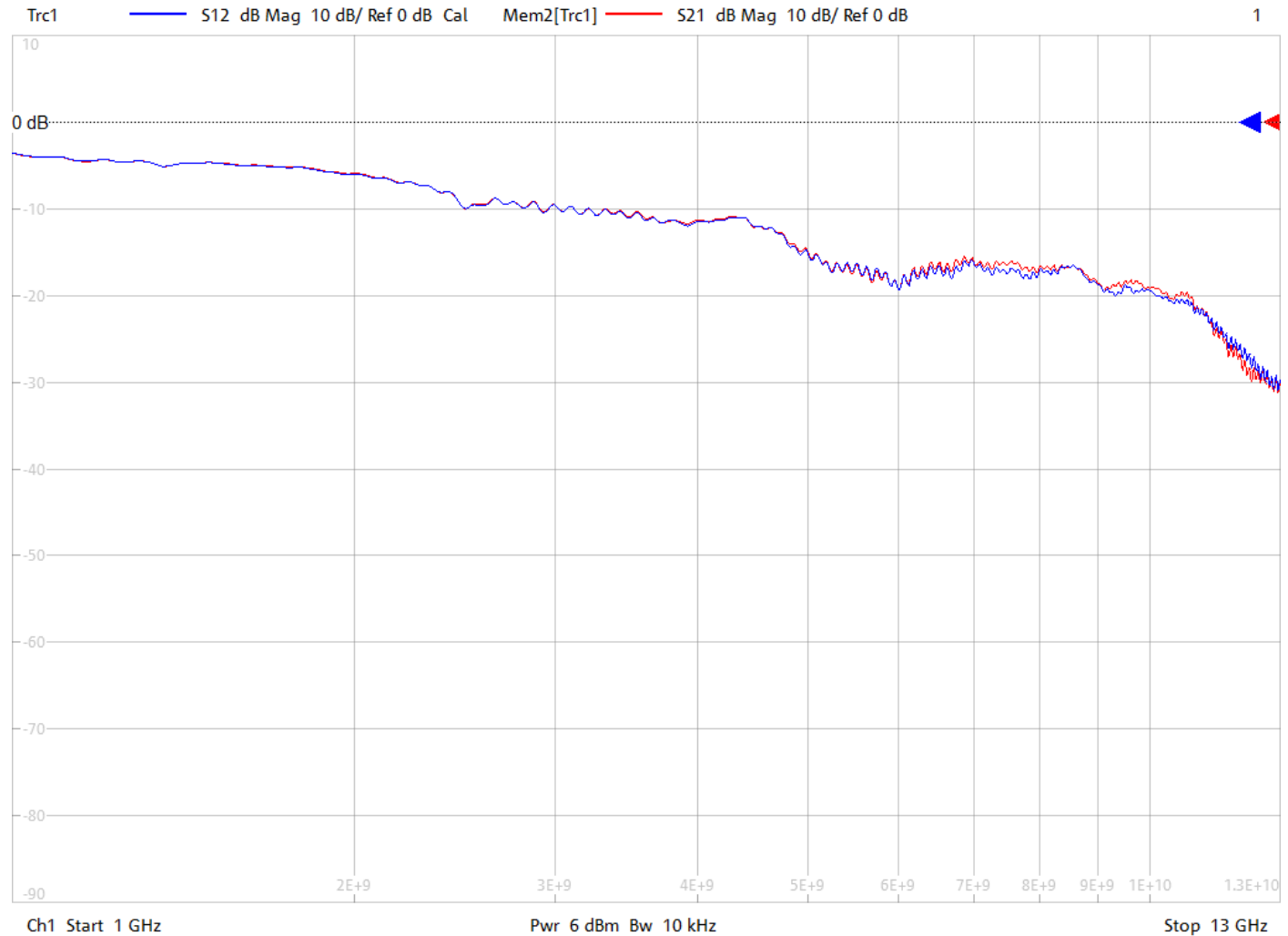


Specification, Requirements & Performances

RF behavior



Attenuation:

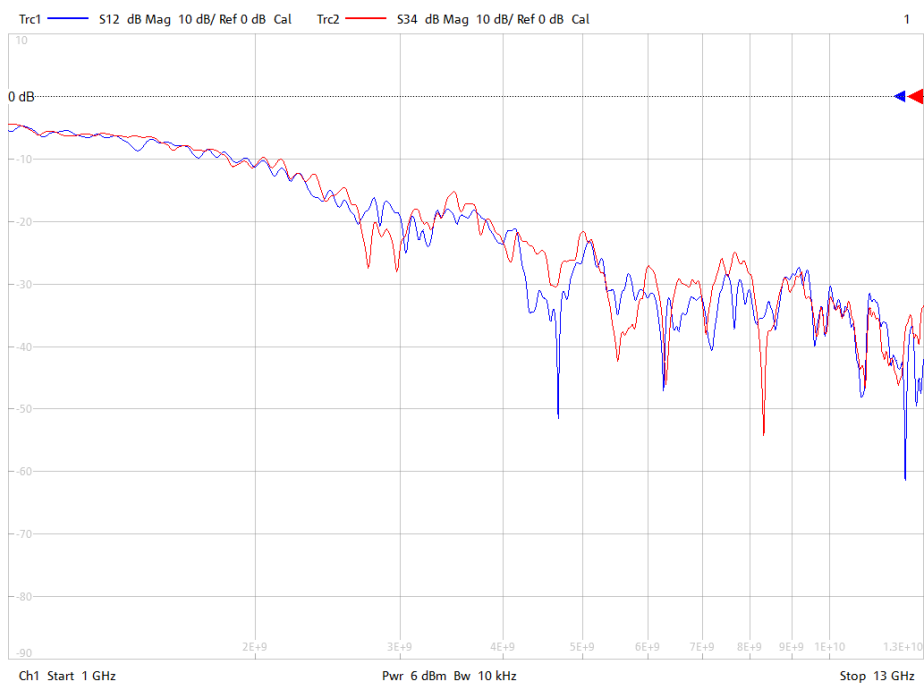


Specification, Requirements & Performances

RF behavior



Attenuation D1 – D1:
(S12 – S34)



Attenuation D2 – D2:
(S32 – S41)



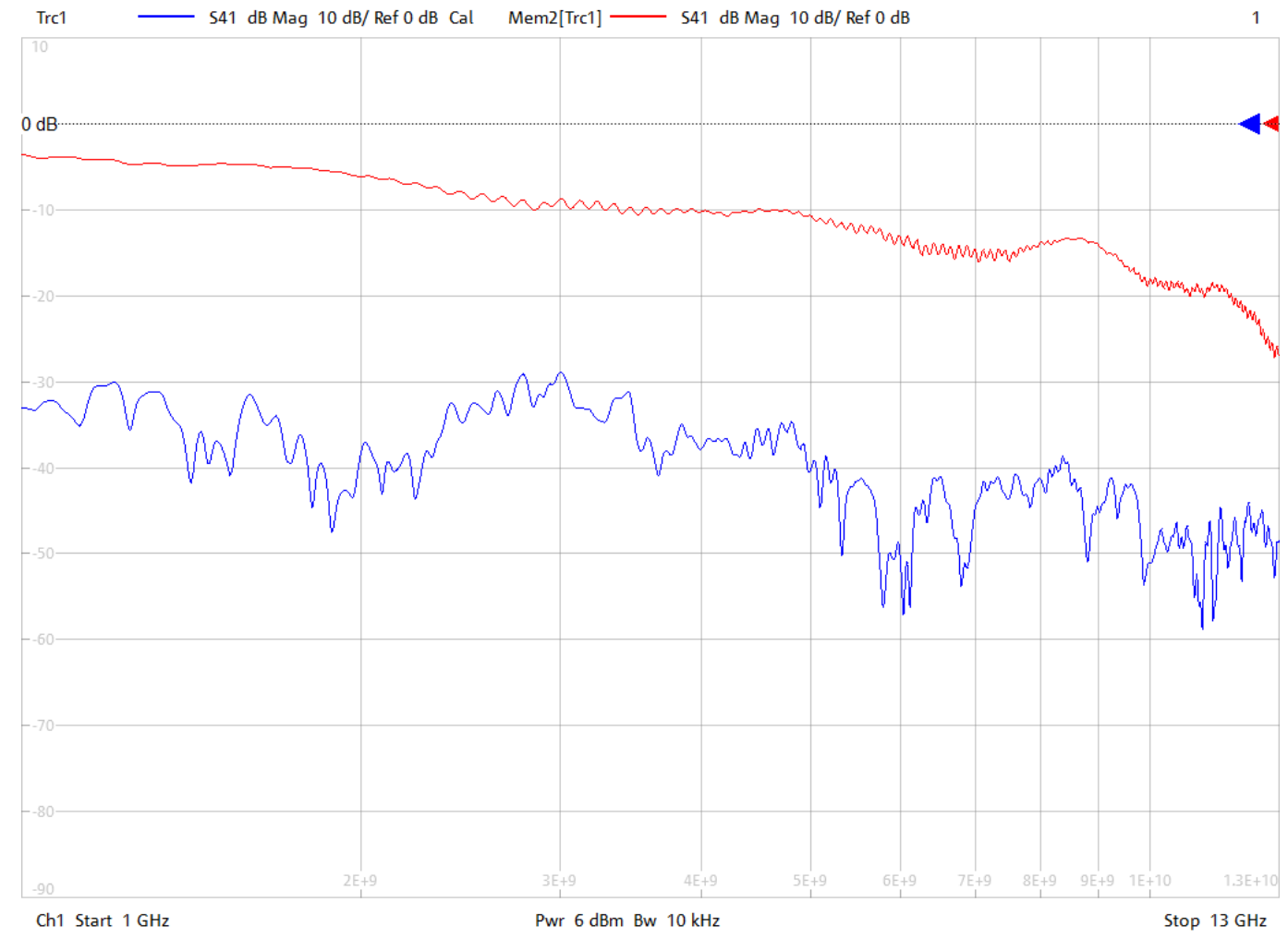
Pairs of datalines are nearly simmilar!

Specification, Requirements & Performances

RF behavior



Attenuation and crosstalk:



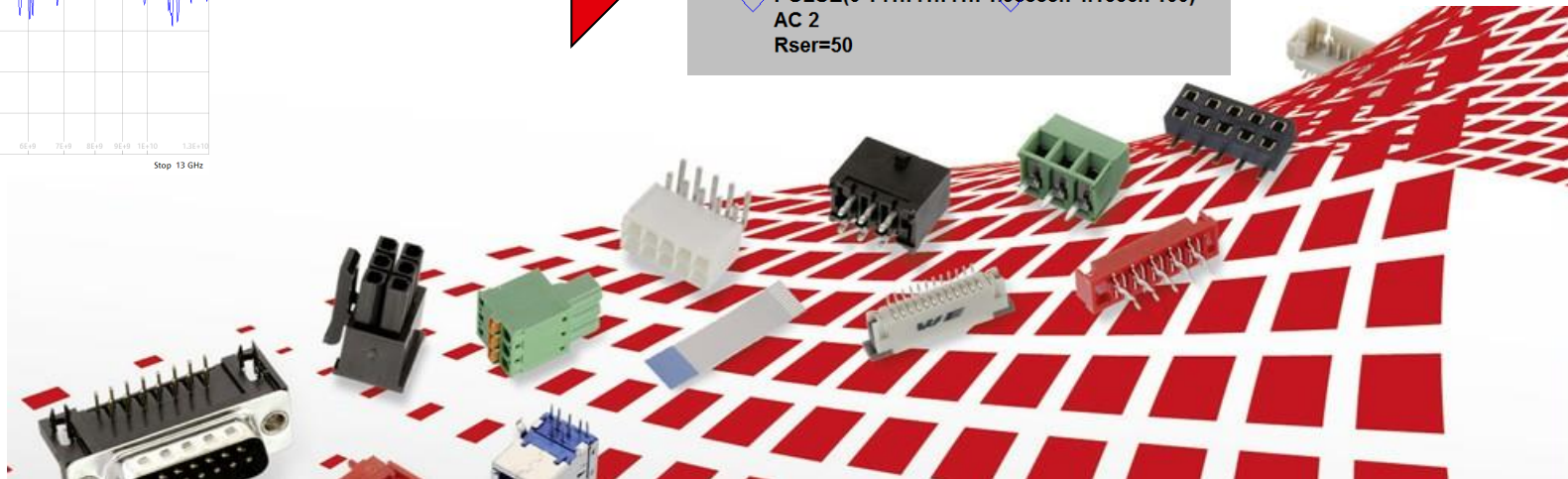
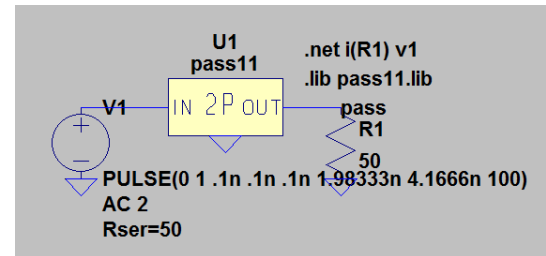
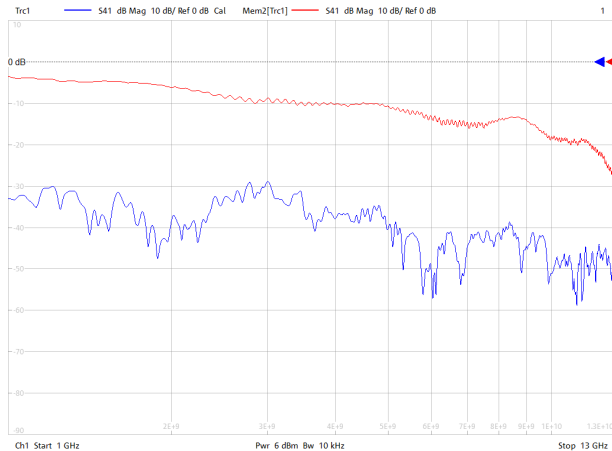
Specification, Requirements & Performances

RF behavior



Integration of measurement in LTSpice:

integrating a set of parameter



Specification, Requirements & Performances

RF behavior



Integration of measurement data:

WHY ?

- For many RF-components an LT-Spice model is not available
- For nearly every RF-component S-Parameter sets are available
- You can find a s2spice-converter at LTSpice-Group
<http://tech.groups.yahoo.com/group/LTspice/files/%20Tut/S-Parameter/S-Parameter%20to%20SPICE/>
- The S2spice-converter changes S-Parameter sets in touchstone format to LTSpice library data sets

Advantages of this USB 3.1 c type connector

Features



Key features of this new connector:

- Higher durability
- Higher data rate
- Higher current capability (Power supply)
- Reversibility feature
- Short Type (for integrated applications)

Compatibility with different protocols:

HDMI

Thunderbolt...



Advantages of this USB 3.1 C type connector

Features

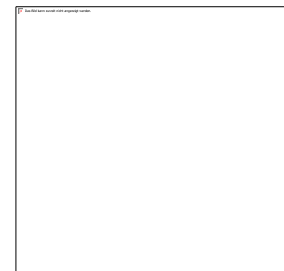
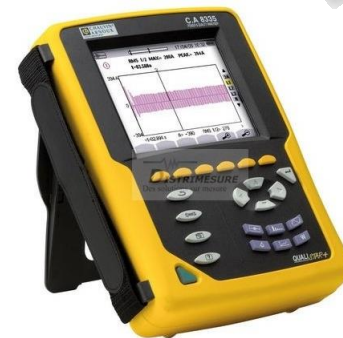
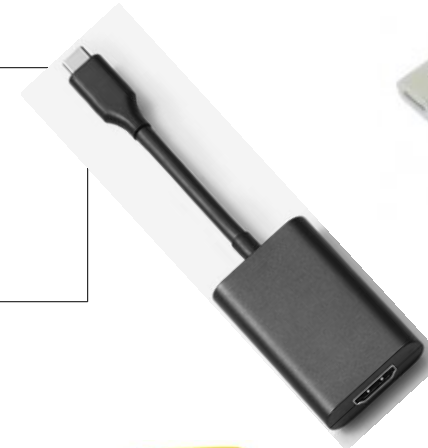
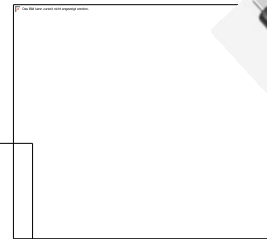
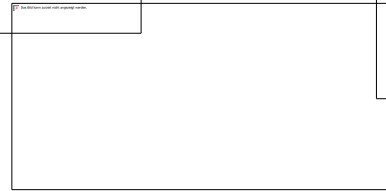
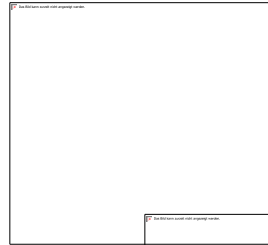


- How to increase data rate?
 - Improve EMC performances: Shielding change
 - Protocol modification: $\approx 20\%$ additional BandWidth (BW)
 - 5 Gbps for Gen 1 in 8b/10b code
 - 10 Gbps for Gen 2 in 128b/132b code
 - Change of polynomial scrambling / encoding
 - Decrease tolerable Jitter regarding USB 3.0 for maintaining BER at 10^{-12}
 - From 200ps to 100ps on all Tx-Media-Rx chain
 - Including crosstalk & ISI after equalization

Where to use it ?

Applications for USB (3.1 C type)

- USB Sticks
- Adapters
- Mouse
- Keyboards
- Hard drives
- Printers
- Video / Camera
- Mobile phones
- Set-top Boxes
- Medical equipment
- Industrial testers



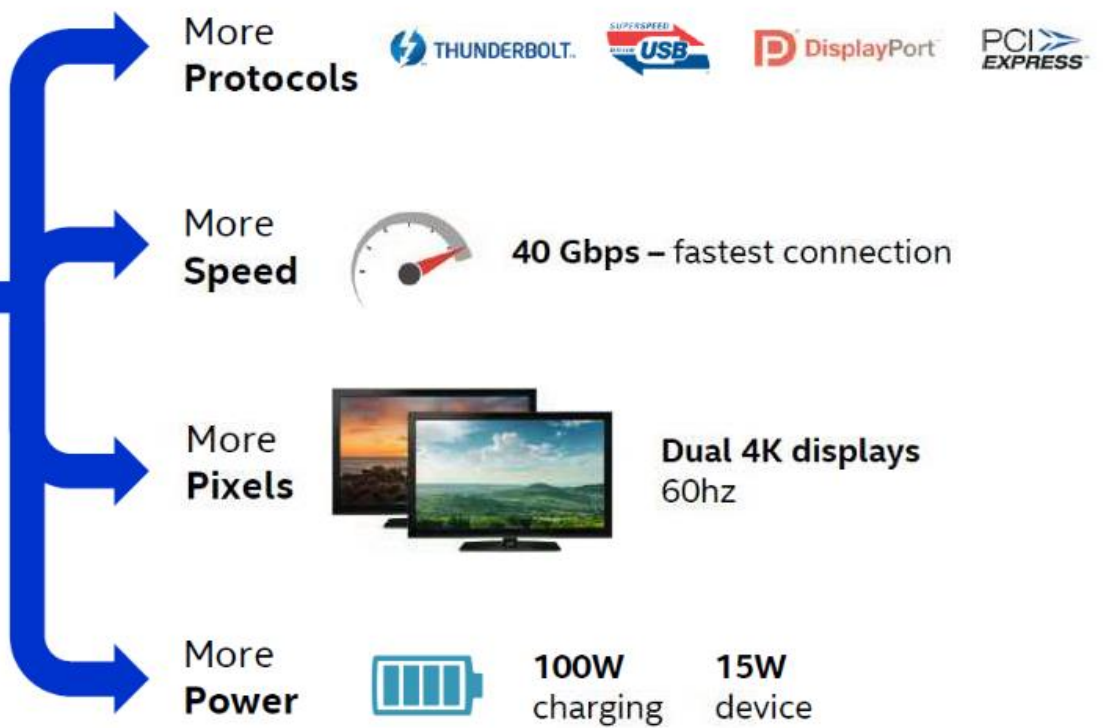


Where to use it ? Applications for USB (3.1 C type)

Thunderbolt™ 3 Brings Thunderbolt to USB-C



The USB-C that does it all.

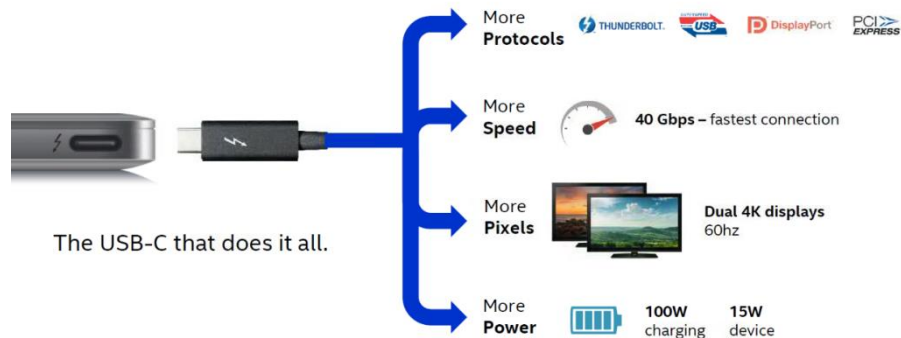


Source: <https://www.golem.de/news/ueberblick-wir-entwirren-den-kabelsalat-um-usb-typ-c-1601-118667.html>

Conclusion

Applications for USB (3.1 C type)

Thunderbolt™ 3 Brings Thunderbolt to USB-C



Source: <https://www.golem.de/news/ueberblick-wir-entwirren-den-kabelsalat-um-usb-typ-c-1601-118667.html>

Mechanical Performance

- 10.000 mating cycles
- High extraction (retention) force
- Long time reliability
- Time saving (only one type of connector is needed)
- Space saving

RF Behaviour

- high data rate (over 10GHz)
- EMC / EMI protection
- mix mode is possible (e.g. USB 2.0 & I²C; USB 2.0 and DC/DC controller)

Electrical Performance

- 5V / 12V / 20V
- up to 5A
- PD (up to 100W)



Where to use it ?

Applications for USB (3.1 C type)

Where NOT to use it ?

